

TMH Inc.

Q3 Consolidated Financial Results — Supplementary Materials (FY Ending Nov. 2025)

Tokyo Stock Exchange Growth Market / Fukuoka Stock
Exchange Q-Board: 280A
Prepared on October 14, 2025

Note : This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail.

To Our Shareholders

Mr. Taisuke Enami, President & CEO



The semiconductor market is experiencing remarkable growth, driven by technological innovations such as advancements in AI, quantum computing, and the Internet of Things (IoT). The market size is projected to reach one trillion dollars by 2030, underscoring its critical role as a cornerstone of the global economy and industrial development.

In this context, as semiconductor factories around the world continue operations and the cumulative amount of semiconductor manufacturing equipment increases, we believe that the semiconductor manufacturing aftermarket—our area of business—will also steadily expand.

Our company has contributed to the stable operation of semiconductor factories by supporting their supply chains through both engineering solutions and digital platforms. We are driven by a strong sense of mission to revitalize Japan's semiconductor industry—and, more broadly, Japanese manufacturing as a whole. We will continue to take on challenges so that the semiconductor industry can once again become a driving force behind Japan's industrial competitiveness on the global stage. We sincerely ask for your continued support and look forward to your ongoing interest in our efforts and growth.

Executive Summary

Q3 progress muted due to uneven shipment timing of large-equipment projects; full-year tracking to plan.

Revenue for the first nine months (Q3 YTD) increased 78% year on year, reaching 83% of the full-year plan. Operating income for the same period grew 239% year on year, achieving 57% of plan.

We continue to expect full-year results to track the annual plan.

Q3 YTD Results (FY Ending November 2025)

	Full-year plan※	Q3 YTD Results	vs. plan (upper end)	3Q YTD result	Q4 Outlook※
Net Sales	8,366 Million yen	6,929 Million yen (※Prior-year Q3 YTD 3,885 Million yen)	83%	83%	Tracking To plan
Operating Income	366 Million yen	209.1 Million yen (※Prior-year Q3 YTD 61.6 Million yen)	57%	57%	Tracking to plan
Recurring Profit	356 Million yen	198.0 Million yen (※Prior-year Q3 YTD 29.2 Million yen)	56%	56%	Tracking to plan

※ The annual plan figures shown represent the upper end of the range.

※ As the fiscal year ended November 2024 was non-consolidated, standalone figures are presented for reference.

Q3 Business Highlights

① Korea subsidiary: business expansion ② Talent Platform: business rollout

① Korea subsidiary: business expansion

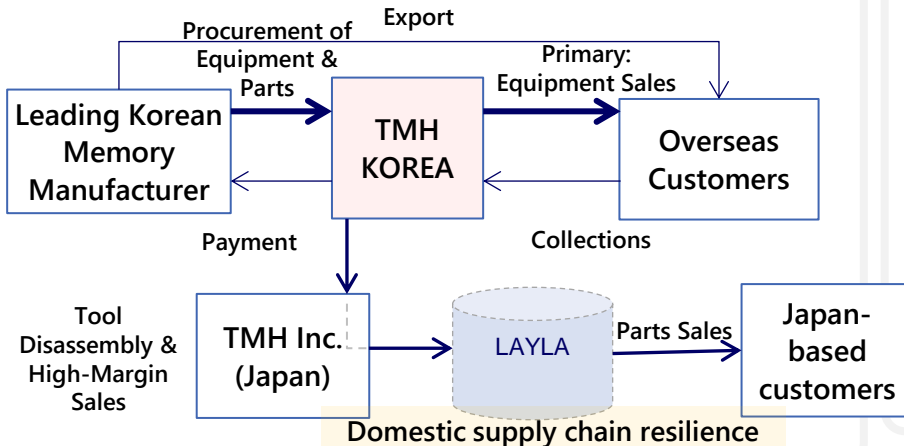
Summary

- Established First Subsidiary in Pyeongtaek, Republic of Korea (July 15, 2025) **Completed**
- Won first order at Korea subsidiary via bid from a leading Korean memory maker
- Strengthen Korea-Based Procurement & Sales; Expand "LAYLA" Cross-Border EC **In Progress**



Business Model

We procure semiconductor manufacturing equipment and parts in Korea, selling equipment mainly to overseas markets and parts primarily in Japan via our parent company.



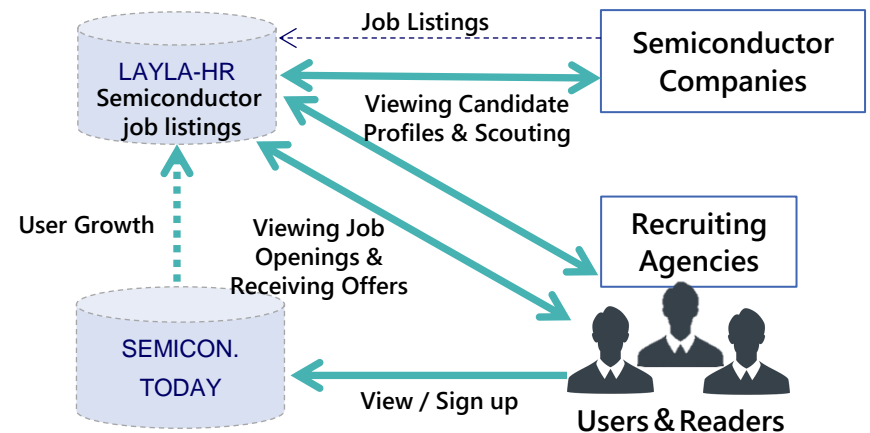
② Semiconductor Media Site (Talent Platform) — Business Expansion

Summary

- LAYLA-HR(December 2024) **Completed**
- SEMICON.TODAY(July 2025)
 - A media site dedicated to the semiconductor industry, providing a wide range of topics including the latest global industry trends, statements and moves by industry leaders, government policy directions across countries, and key statistical data.
- Scheduled to Exhibit at SEMICON India 2025(September 2025)
 - From the venue: Real-time dispatches of local, on-the-ground information.

Business Model

Drive Talent Platform User Growth via Integration of LAYLA-HR and SEMICON.TODAY



AGENDA

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3Q Consolidated Financial Results Briefing for the Fiscal Year Ending November 2025

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Overview of Our Business

1. Company Overview
2. Business Description
3. Market Environment
4. Competitive Landscape
5. Growth Strategy

Appendix

SEIZE THE FUTURE

For FY2025, with the slogan "**SEIZE THE FUTURE**," we have set the goal of establishing our position in the industry through expanding market share and actively pursuing new businesses. Our aim is to "**create the future**" while simultaneously "**capturing the market**."

Establishing a leading position in the maintenance industry through market share expansion.

- Stable growth of core businesses (parts sales and repair services utilizing cross-border e-commerce platforms)
- Market share expansion through scaling up (equipment sales and services leveraging engineering capabilities)

"Creating the Future" through the Promotion of New Businesses

- Enhancing overseas sales capabilities and engineering strength through strengthened alliances with global companies.
- Contributing to the semiconductor industry through the launch of new platform businesses.

Promoting efficiency through infrastructure development.

- Improving productivity through the utilization of AI.
- Implementation of internal systems related to business process improvement.

Full-Year financial Forecast

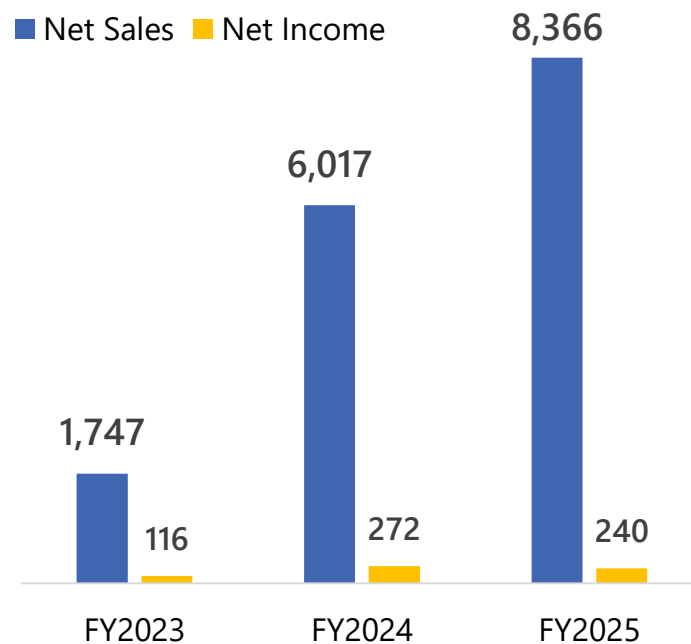
By adapting to external environments and transforming internal operations, we aim to achieve record-high net sales and ordinary income.

Due to increased equipment sales services and parts sales and repair services, FY2025 net sales are forecasted at 8.36 billion yen (YoY +39%), and ordinary income is expected to be 350 million yen (YoY +16%).

While there are positive developments such as the expansion of the AI semiconductor market, Kioxia's IPO, and the completion of JASM (TSMC), the market environment remains mixed due to factors like investment restraint in the Chinese semiconductor market. In this context, we aim to strengthen our business through enhanced engineering capabilities via partnerships with overseas companies and the launch of the new platform LAYLA-HR.

(Unit: Million yen)	Fiscal Year				
	FY2024 Actuals※	Minimum Estimate	FY2025 Maximum Estimate	YoY Change Amount	YoY Change Rate
Net Sales	6,017	7,871	8,366	+2,349	+39%
Operating Income	323	296	366	+42	+13%
Recurring Profit	306	286	356	+50	+16%
Net Income	272	192	240	-31	- 12%

※ As the fiscal year ended November 2024 was non-consolidated, standalone figures are presented for reference.



The Maximum Estimate for FY2025 represents our full-year earnings forecast as currently expected. The Minimum Estimate reflects the scenario in which revenue from a large project scheduled for November 2025 is deferred to the next year.

Progress vs. Forecast

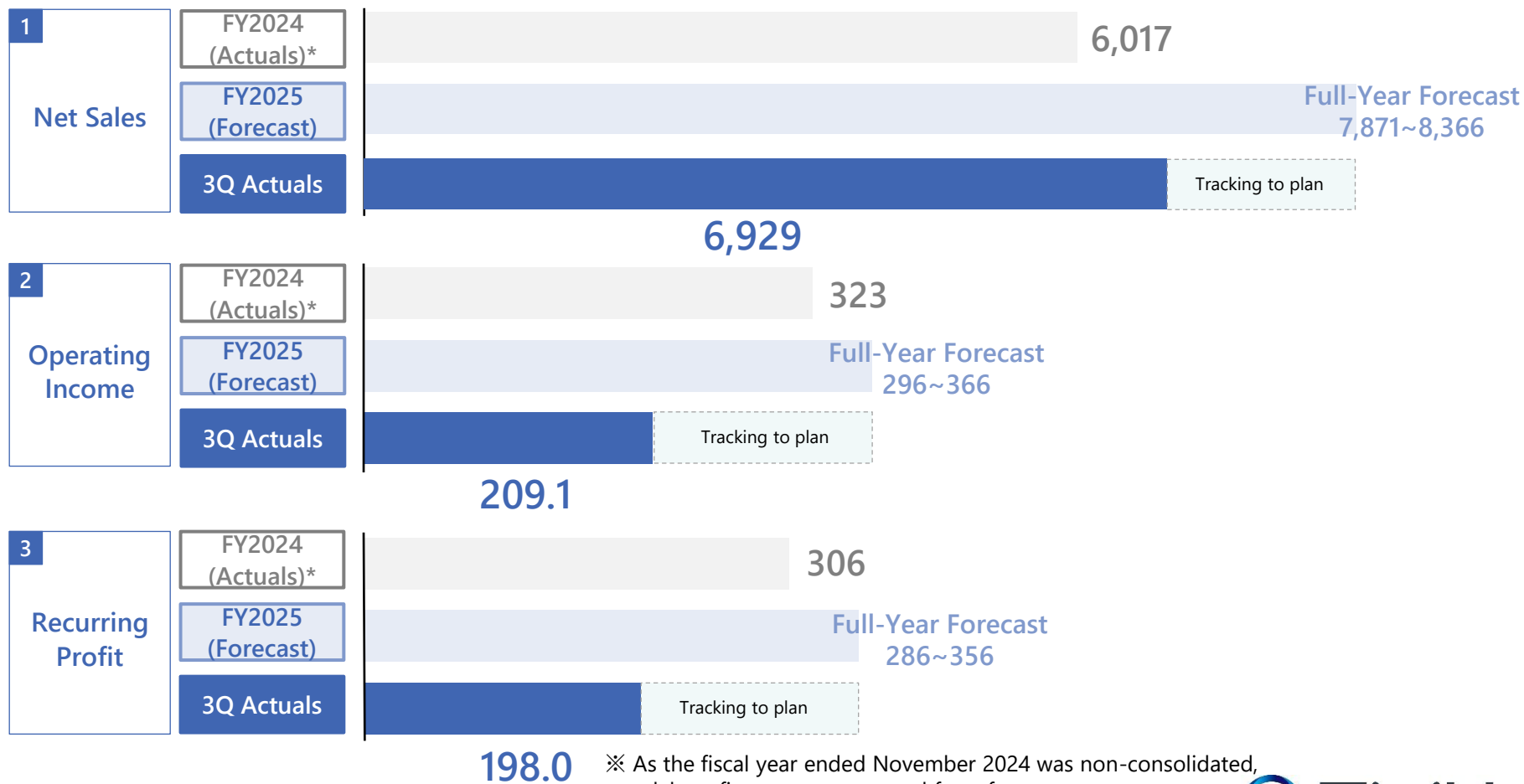
Q3 progress muted due to uneven shipment timing of large-tool projects; full year tracking to the annual plan.

Revenue: On a Q3 YTD basis, exceeded the prior full-year result, driven by growth in engineering-led equipment sales.

Profit: Progress remained muted due to variability in the shipment timing of large equipment projects.

Full year: Tracking in line with the annual plan.

(Unit: Million yen)



※ As the fiscal year ended November 2024 was non-consolidated, standalone figures are presented for reference.

Business KPIs

On a Q3 Basis, Productivity Metrics Improved Significantly with Revenue Growth

Prior-year Q3-end backlog: Elevated, reflecting a concentration of equipment sales in **Q4** of the prior fiscal year.

Current Q3-end backlog: Lower, due to a concentration of equipment sales in **Q2** of the current fiscal year.

Action/Outlook: Actively increasing order intake to rebuild backlog toward **Q4** and into the **next fiscal year**.

(Unit: Million yen)

KPI		End of Q3 FY2024※	End of Q3 FY2025	YoY change (%)
Forward-Looking Performance Metrics	Total Order Backlog	6,617	1,680	-75%
Backward-Looking Performance Metrics	(Cross-Border E-Commerce Platform) Sales Revenue from Parts Sales and Repair Services	668	765	+15%
	(Engineering Services) Sales Revenue from Equipment Sales Services	3,212	6,161	+92%
Productivity Metrics	Revenue per Employee	102	169	+65%
	Net Income per Employee	0.7	3.3	+347%

※FY2024 (ending Nov. 2024) was non-consolidated; parent-only figures are shown for reference.

Backlog is the total value of signed orders expected to be recognized as future revenue; a higher backlog suggests stronger future results.

Financial KPIs

The shareholders' equity ratio improved significantly, reflecting the capital increase associated with the stock exchange listing and net income recorded for the period.

Cash and deposits declined temporarily due to decrease of contract liabilities(customer advances) , and supplier payments, while the equity ratio rose significantly following the IPO and net income.

Key KPIs		FY2024 Year-end	End of Q3 FY2025	YoY Change (%)	Notes (JPY thousands)
Current ratio		124.1%	176.4%	+52%	Increase mainly due to a decrease in contract liabilities (customer advances)
Equity ratio		20.5%	43.4%	+23%	Increase due to lower contract liabilities and higher net assets.
Tangible equity ratio		37.8%	54.8%	+17%	※Adjusted equity ratio excluding the portion of contract liabilities

Balance Sheet		FY2024 Year-end	End of Q3 FY2025	YoY Change (%)	Notes
Current assets		3,551,839	2,758,754	-793,085	
	Cash and deposits	2,562,456	864,907	-1,697,549	Decrease in customer advances related to large equipment sales. Decrease driven by payments to suppliers for large equipment sales.
	Inventory	447,802	1,107,412	659,610	Increase due to variations in the shipment sequence for certain large equipment projects.
Non-current assets		265,344	272,037	6,693	
Total assets		3,817,184	3,030,792	-786,392	
Current liabilities		2,861,694	1,563,525	-1,298,169	
	Accounts payable	803,513	722,146	-81,367	
	Contract liabilities	1,748,807	628,691	-1,120,116	Decrease associated with current-period revenue recognition for large equipment sales
Non-current liabilities		173,724	151,583	-22,141	
Equity		781,766	1,315,683	533,917	Increase due to the capital increase associated with IPO and net income

※FY2024 (ending Nov. 2024) was non-consolidated; parent-only figures are shown for reference.

Business Update

We achieved substantial progress in expanding market share, while platform build-out and core infrastructure remained on track.

All initiatives are tracking well toward achieving “SEIZE THE FUTURE,” with both opportunity seeding and groundwork build-out progressing smoothly.

FY2025 (Year Ending November) Targets and Progress

Gain Share Establish a Leadership Position in the Maintenance (MRO) Industry

We expect expansion overseas on both sides—customers and suppliers.

Showing strong progress

- **Korea market entry:** Local subsidiary established; targeting sales expansion. Acting as an authorized distributor for Korean equipment makers. Participating in equipment tenders from memory manufacturers
- **India market entry:** Commercial negotiations are progressing.
- **Others:** Partnership initiatives underway to drive business expansion.

New Business Development “Creating the Future”

Strengthening
Partnerships
Launch of a New Platform

On track

- **Advancing the build-out of a semiconductor talent platform to address the industry’s talent shortage**
 - Launched the first release of **LAYLA-HR**
 - Launched a new industry media outlet, “**SEMICON.TODAY**”

Driving efficiency via foundation/infrastruct ure build-out

AI Utilization
System Optimization

On track

- Currently advancing under the following projects:
- Strategy formulation
 - Improving the accuracy/quality of deliverables
 - Accumulating and leveraging internal knowledge
 - Streamlining meeting operations
 - Strengthening integration among core systems

AGENDA

01

**3Q Consolidated Financial Results
Briefing for the Fiscal Year Ending
November 2025**

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Overview of Our Business

1. Company Overview
2. Business Description
3. Market Environment
4. Competitive Landscape
5. Growth Strategy

Appendix

02 Overview of Our Business

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- 02 Business Description
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Corporate Profile

Company Name TMH Inc.

President & CEO Taisuke Enami

Head Office 3-14-6 Shimogorikita, Oita City, Oita Prefecture, Japan

Established March 9, 2012

Number of Employees 41 (as of the end of August 2025)

Capital 299.09 million yen
(as of the end of August 2025)

Business Description Semiconductor Manufacturing Field Solutions
(Sales and repair of equipment and components, operation of cross-border e-commerce site LAYLA-EC)

Offices Oita Head Office, Chubu Branch(Mie),Kanto Branch(Tokyo),Tohoku Sales Office(Iwate),Kyushu Branch (Kumamoto)

Overseas subsidiary TMH Korea Inc. (Pyeongtaek, South Korea)

Network: 5 sites in Japan and South Korea



Management Team

Our management team consists of experts in semiconductors and supply chains, formed to address the shortage of specialists in semiconductor manufacturing equipment.



榎並大輔 Taisuke Enami
President & CEO

After graduating from Waseda University, he joined Toshiba Corporation. While at Toshiba, he recognized challenges in supplier management and decided to start his own business. Since founding the company, he has achieved continuous revenue growth. In 2020, he was selected by Oita Prefecture as a regional leading entrepreneur.



香月賢一 Kenichi Katsuki
COO

After joining Toshiba Corporation, he engaged in purchasing and procurement for over 20 years. In 2012, he was assigned to the centralized components procurement department at Toshiba's headquarters, where he achieved cost reductions and improvements totaling several billion yen annually. He joined TMH in 2016.



関真希 Maki Seki
CFO

He worked on business transformation at a major operating company and Deloitte Tohmatsu Consulting. He was involved in numerous projects from a supply chain perspective, including global cost structure visualization and M&A. He joined TMH in 2015.



野木村修 Osamu Nogimura
Outside Director

After graduating from Nagoya University, he joined Hitachi, Ltd. He served as General Manager of the Production Headquarters at Renesas Technology, Executive Officer and General Manager of the Production Headquarters at Renesas Electronics and President & CEO of Renesas Semiconductor Package & Test Solutions. He has consistently worked in the semiconductor manufacturing sector throughout his career.

Company Introduction

A leading company providing diverse support for the operation of semiconductor fabs within the semiconductor industry.



A leading company dedicated to solving the diverse social challenges confronting the semiconductor industry.

Business area

Massive Semiconductor Industry

Value Provided

**Extension of Semiconductor Manufacturing Equipment Lifespan
Reduction of Maintenance Costs**

Features

Niche market leader with strong growth

Why Our Company Is Needed

Aging semiconductor fabs are burdened with a wide range of supply chain issues.

Procurement Challenges

- Many semiconductor factories in Japan are facing **aging and obsolescence** issues, with a high dependency on **legacy manufacturing equipment**. This has made it **increasingly difficult to procure necessary parts**.
- The procurement of parts for legacy semiconductor manufacturing equipment heavily relies on individual know-how and manual processes, **reflecting a significant lag in digital transformation**.

Manufacturing Challenges

- Due to the rapid increase in demand driven by IoT (Internet of Things), the demand **for legacy equipment continues steadily**.
- The prolonged downturn in the domestic semiconductor market has **led to a shortage of engineering talent**.
- In legacy semiconductor factories, **maintenance operations have become highly dependent on individual expertise**, leading to equipment failures that result in quality issues and significant delivery delays.

Logistics Challenges

- The habitual **storage of legacy equipment** purchased for parts retrieval is **constraining production space**.

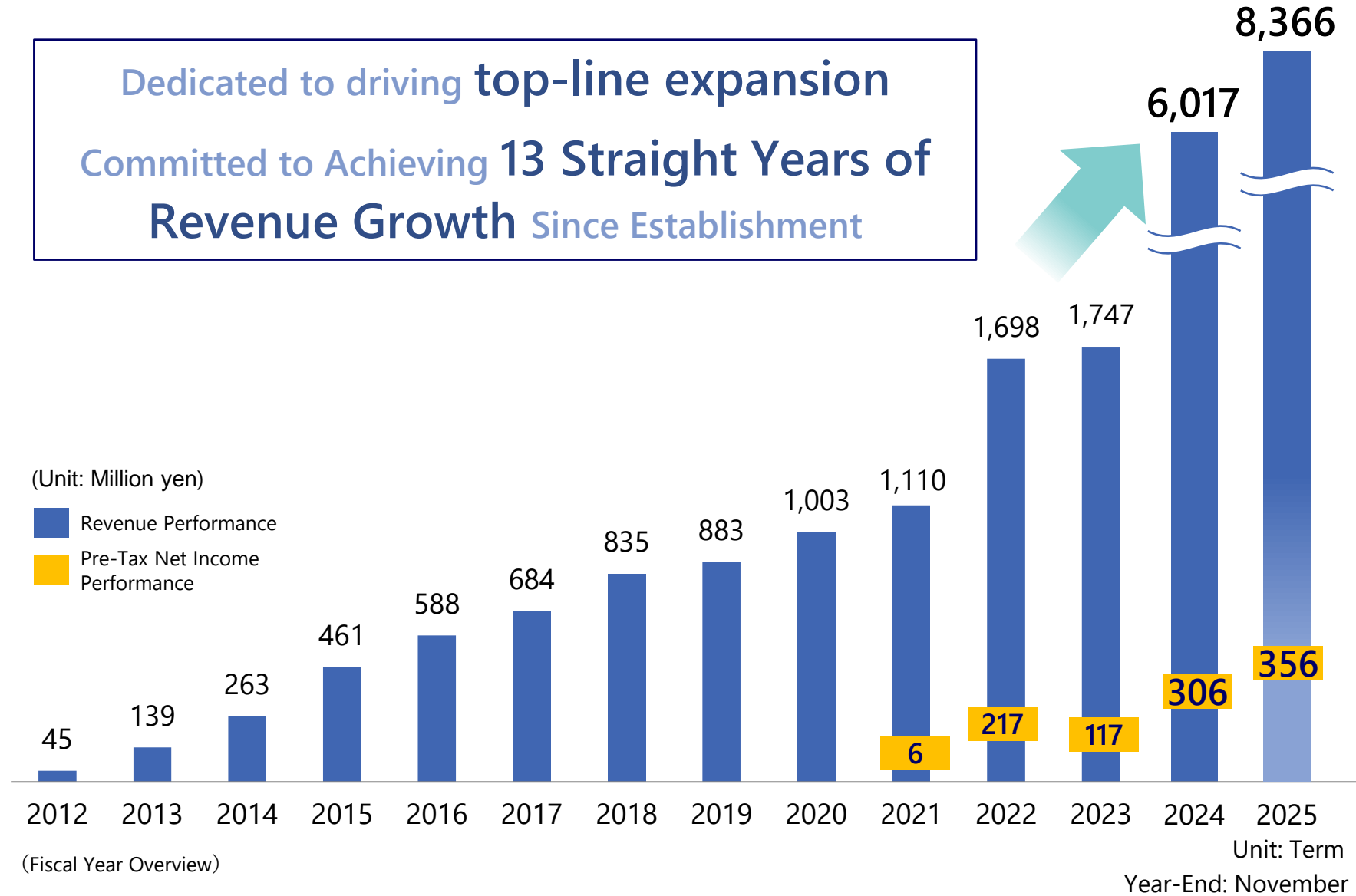
Our Vision for the Future

We aim to resolve the diverse challenges in semiconductor manufacturing and **support the revitalization of Japanese manufacturing.**

Business Performance Trends

We focus on expanding our top-line growth and aim to establish our position as a leading company in the aftermarket market.

Dedicated to driving top-line expansion
Committed to Achieving 13 Straight Years of
Revenue Growth Since Establishment



02 Overview of Our Business

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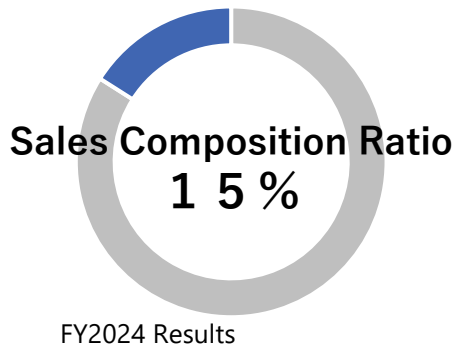
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Business Overview – Semiconductor Manufacturing Field Solutions - We provide total solutions to support the stable operation of semiconductor manufacturing facilities.

Providing Total Solution Services for Semiconductor Manufacturing Facilities

1 Provision of Parts Sales and Repair Services via Cross-Border E-Commerce Platforms

Utilizing the platform for global trading of semiconductor manufacturing equipment and parts



【Services Provided】

- ✓ Supply of rare parts
- ✓ Provision of a wide range of repair services

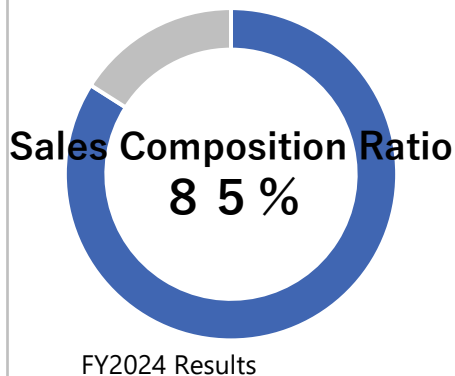
【Achievements】

- ✓ Over 200 high-quality global suppliers (offering diverse maintenance and parts supply)
- ✓ More than 315,000 items available, adopted by over 50% of domestic semiconductor factories



2 Equipment sales services leveraging engineering capabilities

Equipment dismantling, relocation, removal, process tuning, and startup services are provided.



【Services Provided】

- ✓ Providing end-to-end services from dismantling to removal of specialized equipment
- ✓ Yield improvement through process tuning of legacy equipment

【Achievements】

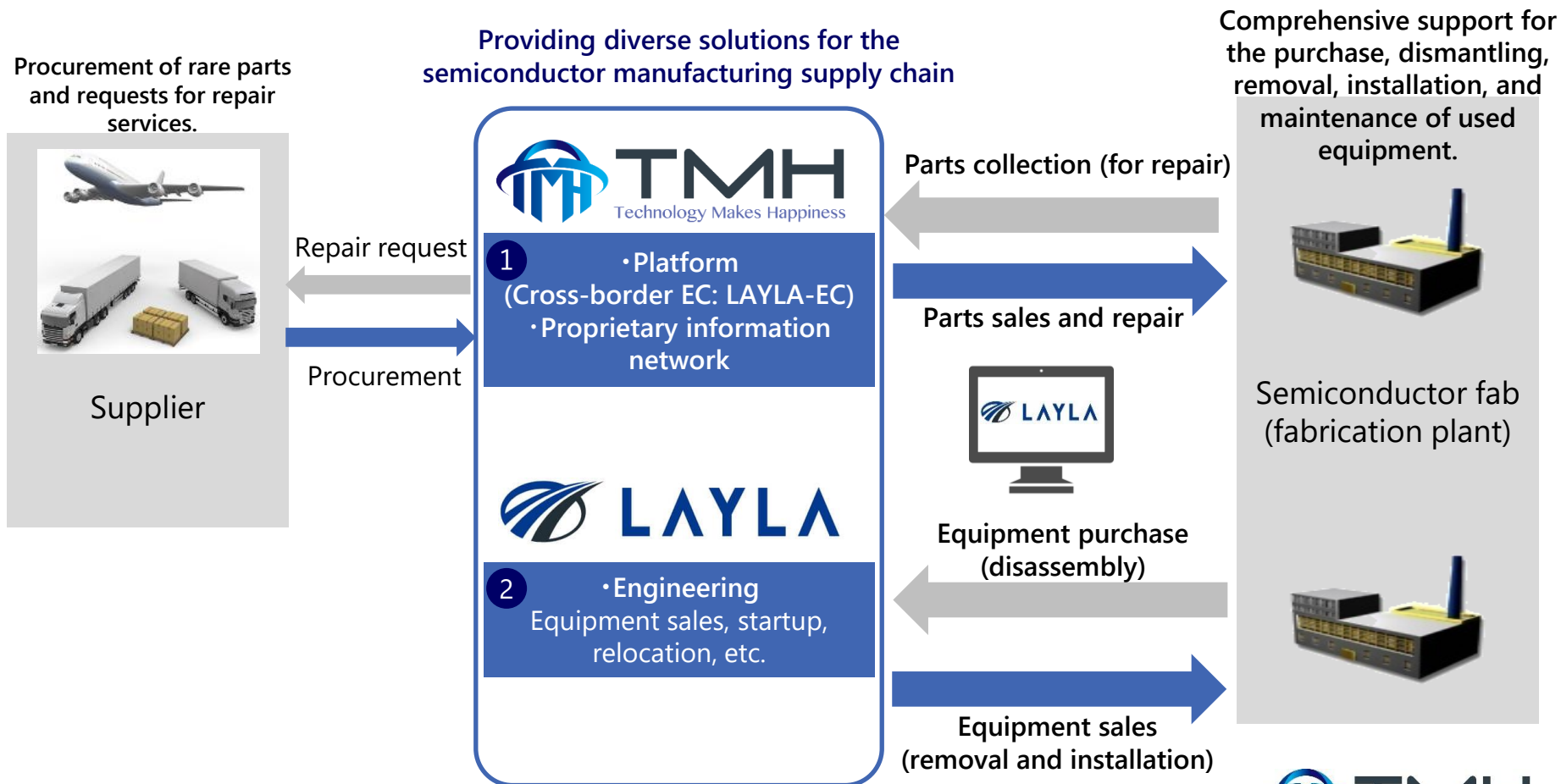
- ✓ Received supplier award from a major U.S. semiconductor manufacturer
- ✓ Proven track record and reliability (over 100 semiconductor manufacturing equipment transactions)



Business Flow

By integrating the EC platform with engineering, we support the sustainable operation of semiconductor fabs.

- Collaborating with engineering companies and suppliers worldwide, we provide a broad range of solutions to address customer challenges, including parts repair and sales, yield improvement, and the purchase of surplus equipment and parts.
- LAYLA aggregates global equipment and parts data to streamline the procurement process, contributing to the efficient operation and sustainability of semiconductor manufacturing equipment in fabs.

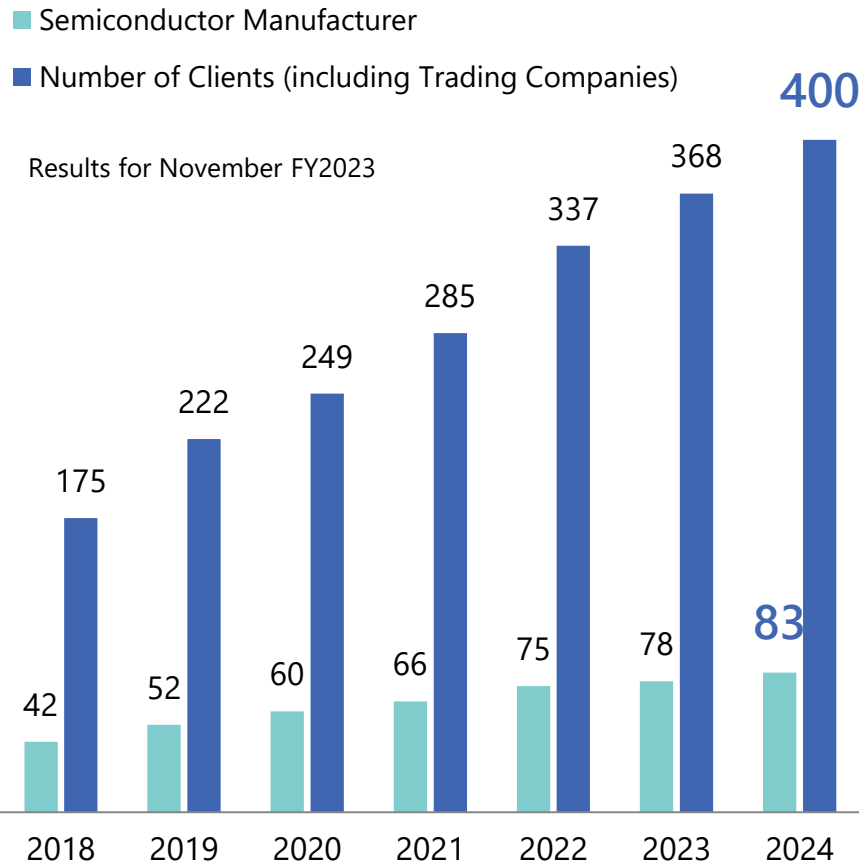


Customers

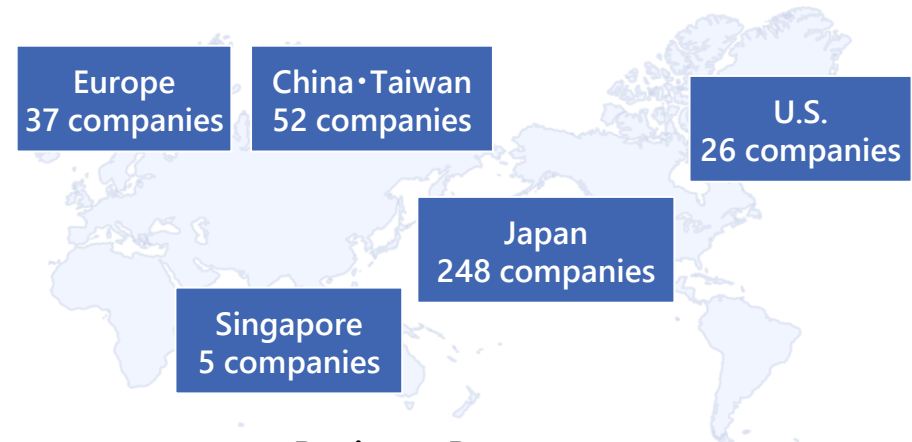
Expanding direct transactions with domestic semiconductor manufacturers through overwhelming procurement capabilities utilizing the cross-border e-commerce platform.

- The number of customers exceeds 70 semiconductor manufacturer sites. Including other clients, the total number of business partners surpasses 300 companies.
- We maintain direct transactions with almost all domestic semiconductor manufacturers.
- The expansion of the cross-border e-commerce platform "LAYLA-EC" has further increased transactions with overseas semiconductor manufacturers, contributing to revenue growth.

Number of Customers Over Time



Global Client Map



Business Partners

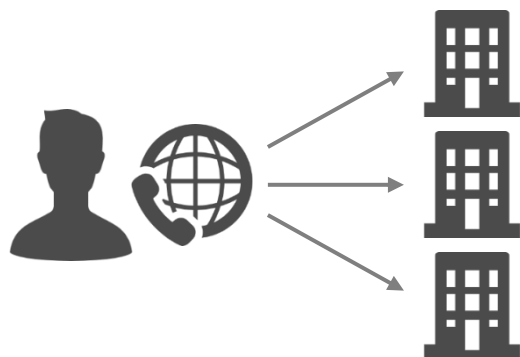
- Kioxia Corporation
- Texas Instruments Incorporated
- Sony Semiconductor Manufacturing Corporation
- Renesas Electronics Corporation
- SUMCO Group
- Toshiba Group
- LAPIS Semiconductor Co., Ltd. and others

The Value Provided by LAYLA

A Platform That Visualizes Global Real-Time Inventory

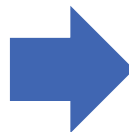
- We provide a platform that enables visibility into actual inventory—something that was difficult to achieve with conventional procurement methods—**streamlining the procurement of semiconductor manufacturing equipment.**

Traditional procurement methods



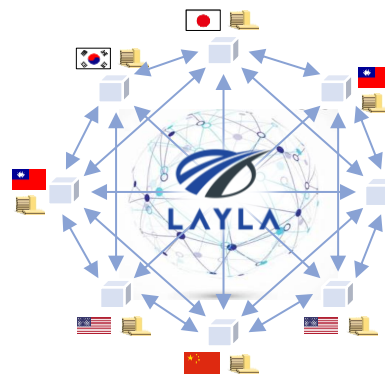
- Buyers must contact each supplier individually to obtain necessary information, which limits access to timely and comprehensive data.
- Traditional procurement methods are time-consuming and costly, often delaying delivery.
- Limited procurement channels force companies to build their own sourcing networks.

Procuring parts for aging manufacturing equipment is becoming increasingly difficult.



LAYLA

Over 315,000 items available



Centralized
access to
globally
dispersed
components.

- **24/7 access to actual inventory data.**
- Real-time visibility into inventory price, lead time, warranty period, and product condition.
- TMH serves as the official sales interface, offering buyers a secure and reliable purchasing experience.

Contributing to the digital transformation (DX) of semiconductor factories

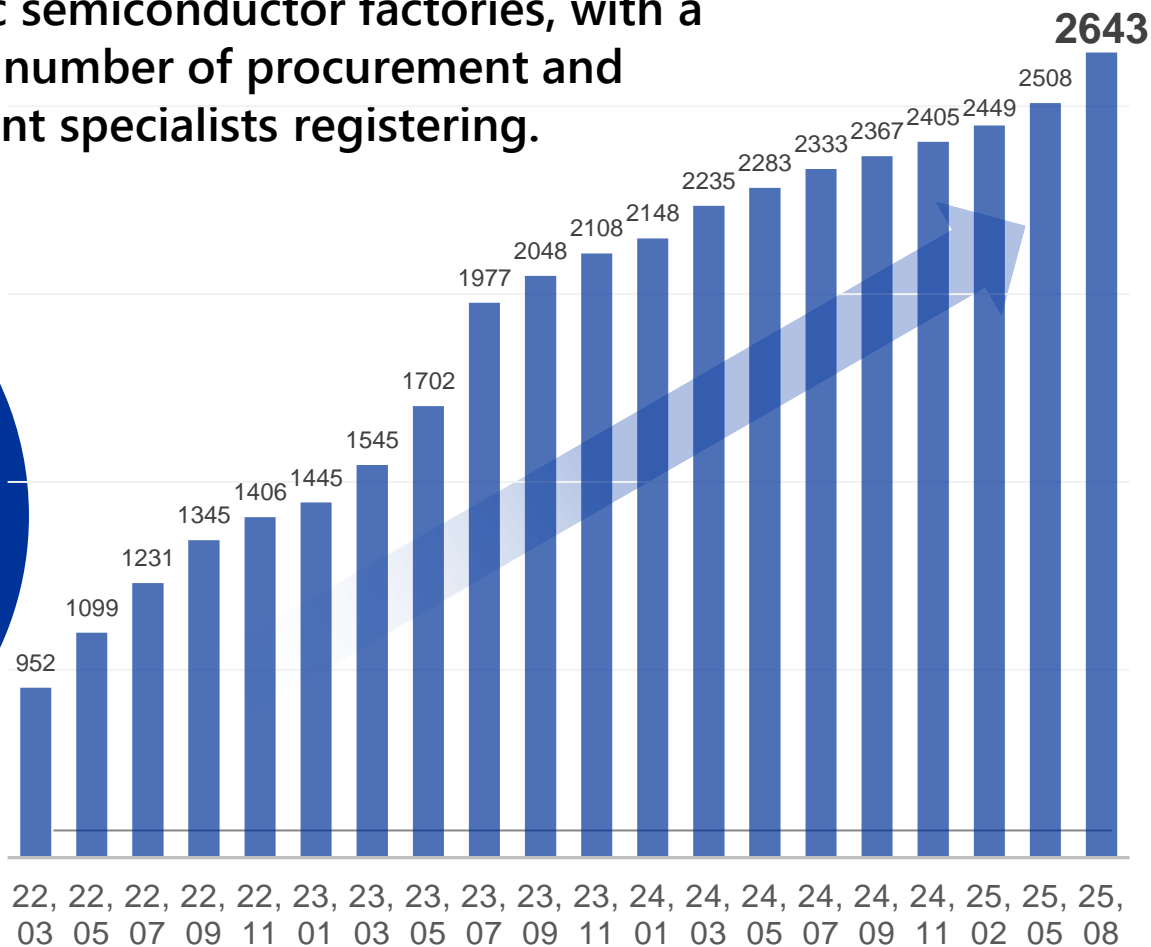
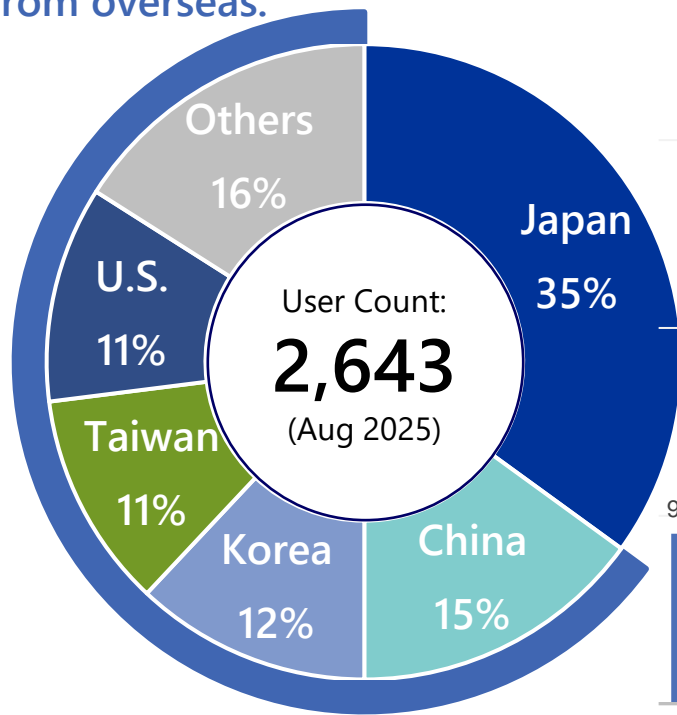
1 Steady Growth in LAYLA-EC Users

The number of LAYLA-EC users continues to grow steadily. While Japan remains the primary user base, many users from overseas have also registered.

User Registration Trends

The adoption of LAYLA-EC is accelerating at domestic semiconductor factories, with a growing number of procurement and equipment specialists registering.

65% of users are from overseas.



The user count represents the total number of both domestic and international buyers and sellers registered on LAYLA.

Equipment Sales Services Leveraging Engineering Expertise

Providing operational support services to semiconductor factories and generating revenue from them.

- Field engineers with deep knowledge of semiconductor equipment configurations and component structures collaborate with engineering firms and suppliers to offer a wide range of solutions addressing customer challenges, including yield improvement initiatives (such as CIP implementation) and purchasing of unused equipment.
- Received **the Regional Supplier Recognition Award** from a major semiconductor manufacturer.



2 Regional Supplier Recognition Award

Among 12,000 suppliers globally, only 20 were honored with the award, signifying recognition of superior technical capabilities.

- Not only do we sell used semiconductor manufacturing equipment to major semiconductor manufacturers, but we also perform equipment commissioning and process tuning, significantly contributing to productivity improvements.
As a result, this leads to substantial cost reductions for the manufacturers.

Advanced Process Tuning and Equipment Commissioning

Contributing to customers' quality improvement and cost reduction.



Fine-tuning various equipment settings and operations to optimize the manufacturing process.

Product Quality Improvement

In semiconductor chips that require fine structures and high precision, optimizing settings reduces errors and defects.

Improvement of Production Efficiency

Process tuning shortens the manufacturing cycle and improves productivity.

Yield Improvement

Improved yield increases the proportion of good-quality products produced.

2

Business Flow Equipment Buy-Sell Process

Having in-house dismantling know-how—the prerequisite to any transaction—accelerates our equipment buy-sell process.



Procurement



Logistics



Sales

Bidding

Sales Contract

Dismantling

Export

Inspection

Invoicing

Decontamination

Shutdown

Cable and Piping Removal

Internal Component Dismantling

Disposal and Sorting

Technical Report

Decontamination

Gas line shutoff and removal
Safe removal of coolant and other fluids

Shutdown

Power disconnection from equipment
Removal of backup batteries

Removal of Cables and Piping

Removal of External Covers
Detachment of Piping and Cables

Dismantling of Internal Components

Individual Removal of Modules and Parts

Disposal and Sorting

Separation of reusable materials
Proper handling of hazardous substances
Appropriate disposal of recyclable waste materials

Technical Report

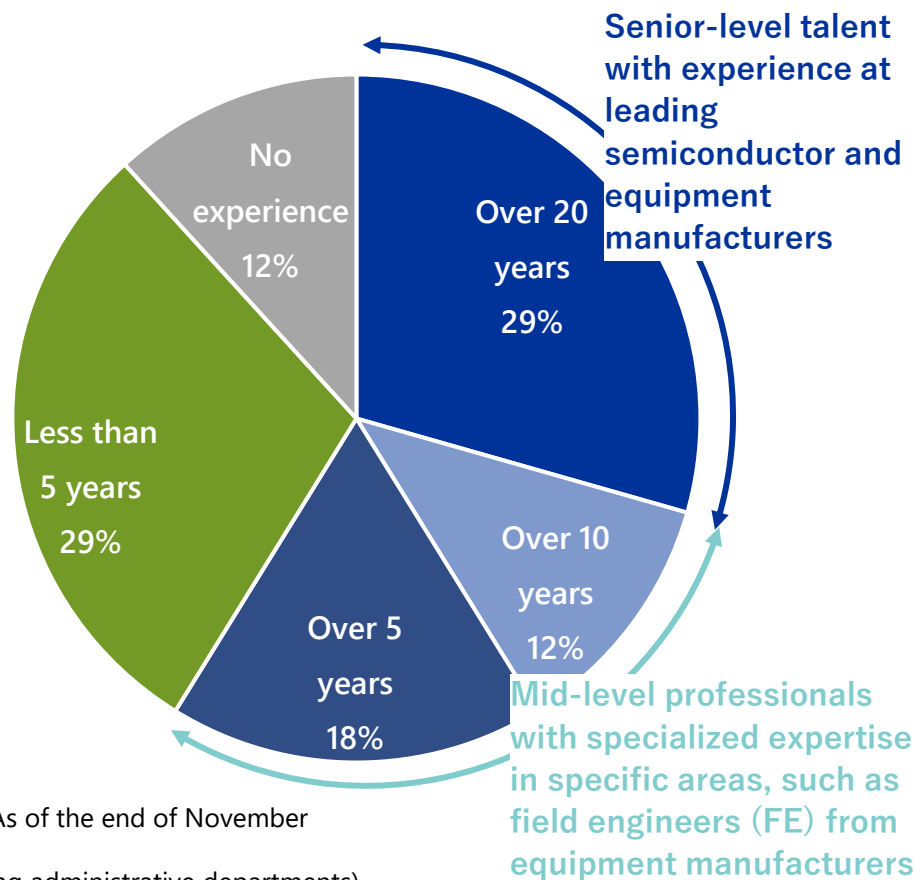
Detailed documentation of work performed
Incident reporting

Equipment Sales Services Leveraging Engineering Expertise

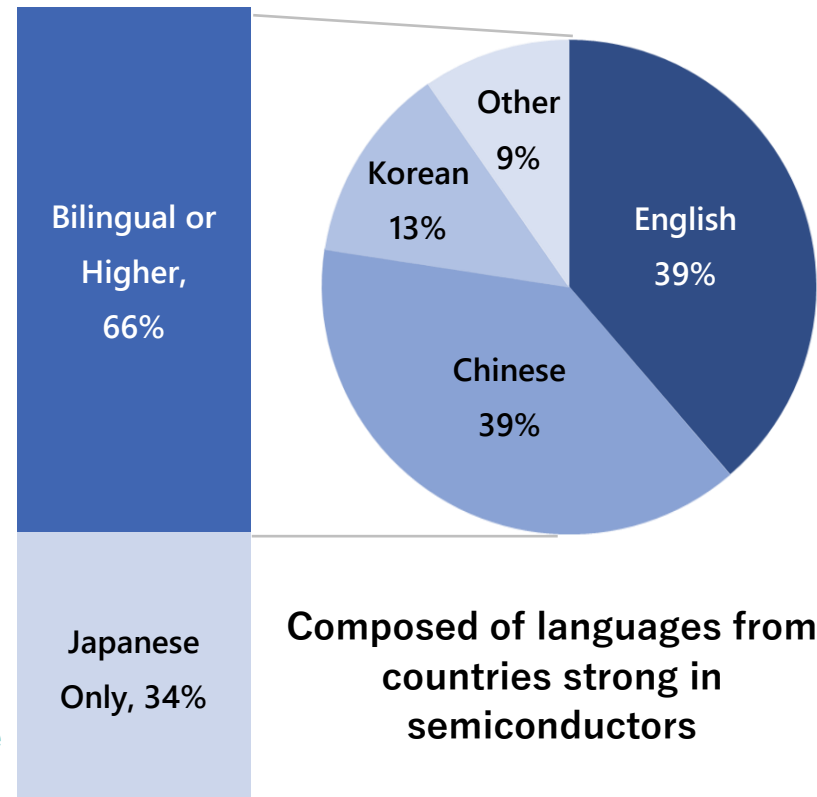
A team of specialists with advanced knowledge and diverse backgrounds

- Our team includes a strong lineup of semiconductor manufacturing professionals, ranging from mid-career experts to seasoned veterans.
- Over 60% of our employees are bilingual, with deep knowledge of local business practices and customs.

Years of Experience in the Semiconductor Industry



Employee Composition by Language



Source: As of the end of November 2024
(excluding administrative departments)

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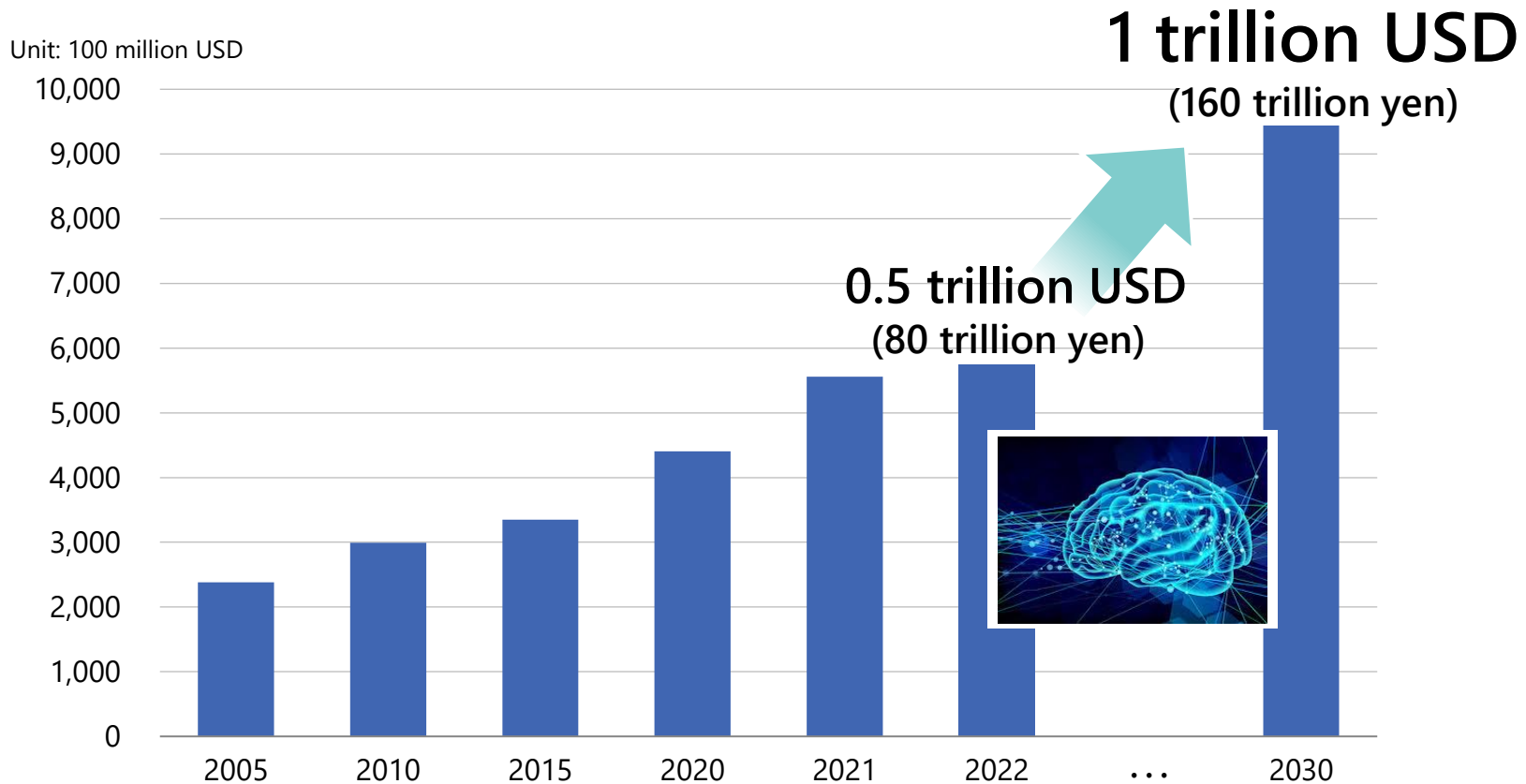
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Global Semiconductor Market Size

The global semiconductor market is projected to grow to 160 trillion yen by 2030.

- Semiconductors are used in AI, 5G, electric vehicles, quantum computers, and various other technologies. Their applications have diversified, leading to rapid market expansion in recent years.

Global Semiconductor Market Forecast



Source : SEMI, May 9, 2022 ISS 2022: Semiconductor Industry Market Outlook and Prospects for Reaching \$1 Trillion by 2030
Ministry of Economy, Trade and Industry (METI) (March 24, 2021), "1st Semiconductor and Digital Industry Strategy Review Meeting"
WSTS, Spring 2024 Semiconductor Market Forecast

Our Business Background: The Importance of Legacy Semiconductor Manufacturing Equipment in the Global Market

There is strong demand not only for “cutting-edge equipment” but also for “legacy equipment” that adapts to diverse applications.

State-of-the-art

Current State of the Semiconductor Market

Advances in AI and cutting-edge technologies have created a demand for high-performance, state-of-the-art semiconductors. Without progress in semiconductors, there can be no advancement in civilization.

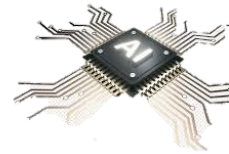


Older Model

With the widespread adoption of consumer-oriented products such as **IoT devices and electric vehicles**, the applications of **semiconductors have diversified**. There is strong demand for low to mid-performance semiconductors as well. Semiconductor manufacturing equipment invested in **over 20 years ago is still actively operating today**.

Investment Trends in the Semiconductor Market (Direction of Corresponding Measures)

Public-private collaboration is driving trillion-yen scale investments in advanced semiconductor development (such as the CHIPS Act, METI subsidies, and TSMC investments).



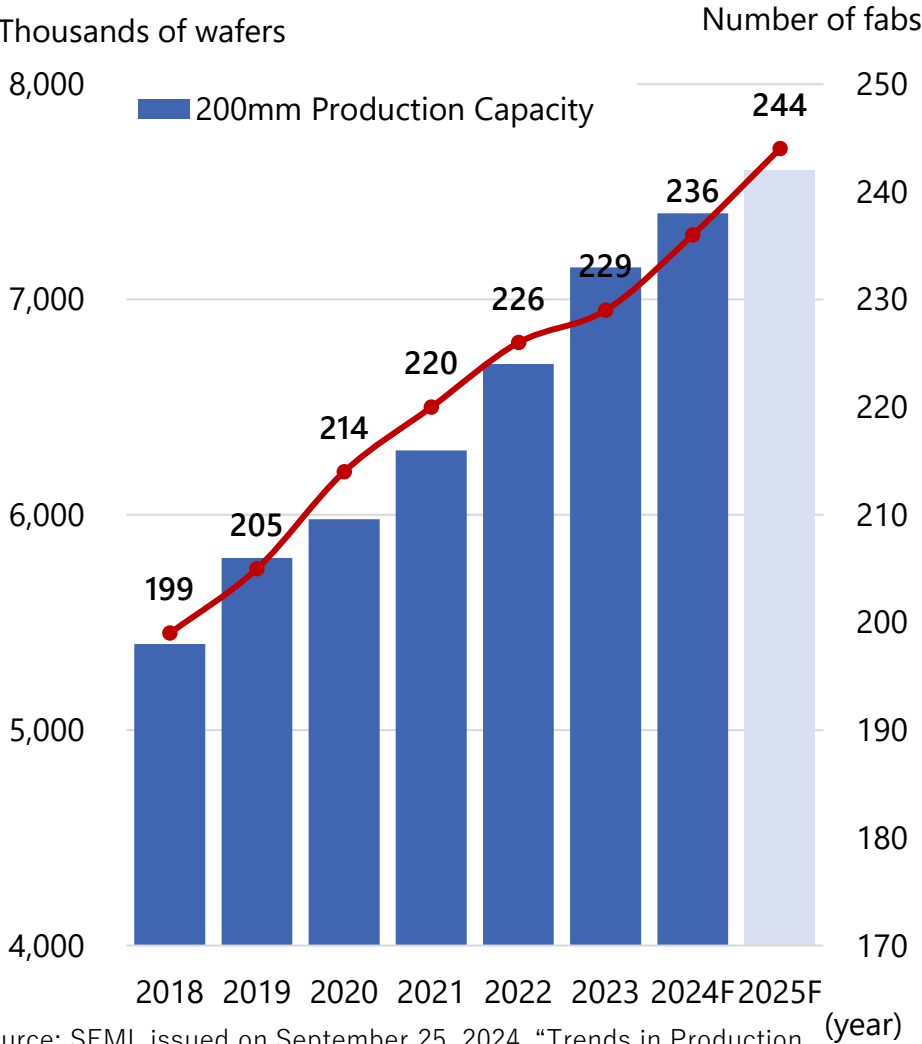
Legacy semiconductor manufacturing equipment remains **highly important** today, and global **investments** are being made in **equipment maintenance**, including procurement of EOL (End-of-Life) parts, repairs, and the purchase, commissioning, and improvement of used equipment.

The maintenance of legacy semiconductor manufacturing equipment is a critical issue, comparable in importance to advanced semiconductor development.

Our Business Background: The Strong Demand for Legacy Semiconductors

Due to the semiconductor shortage, production capacity at 200mm fabs is rapidly growing. Even leading companies rely heavily on legacy semiconductors as a core product.

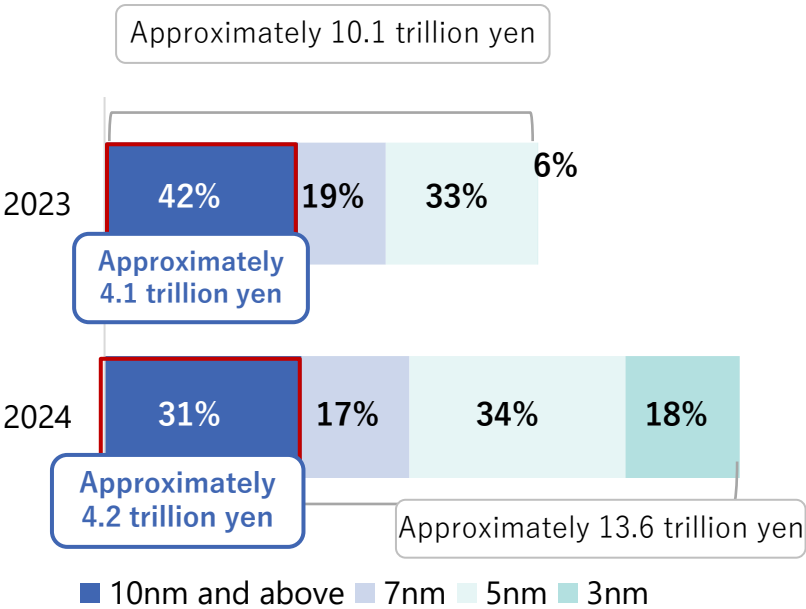
Number of 200mm Wafer Fabs and Production Capacity Trends



Source: SEMI, issued on September 25, 2024, “Trends in Production Capacity at 200mm Semiconductor Front-End Fabs Worldwide”

TSMC Revenue Breakdown by Process Node

While the market share of nodes above 10nm has declined, the total revenue remains substantial.



Exchange Rates Used for Conversion to Japanese Yen
2023: 1 NTD = 4.68 JPY
2024: 1 NTD = 4.73 JPY

Net Sales:
2023: Approximately NTD 2.1 trillion
2024: Approximately NTD 2.8943 trillion

Source: Prepared by our company based on TSMC's disclosed materials (Full-year results for 2023 and 2024)

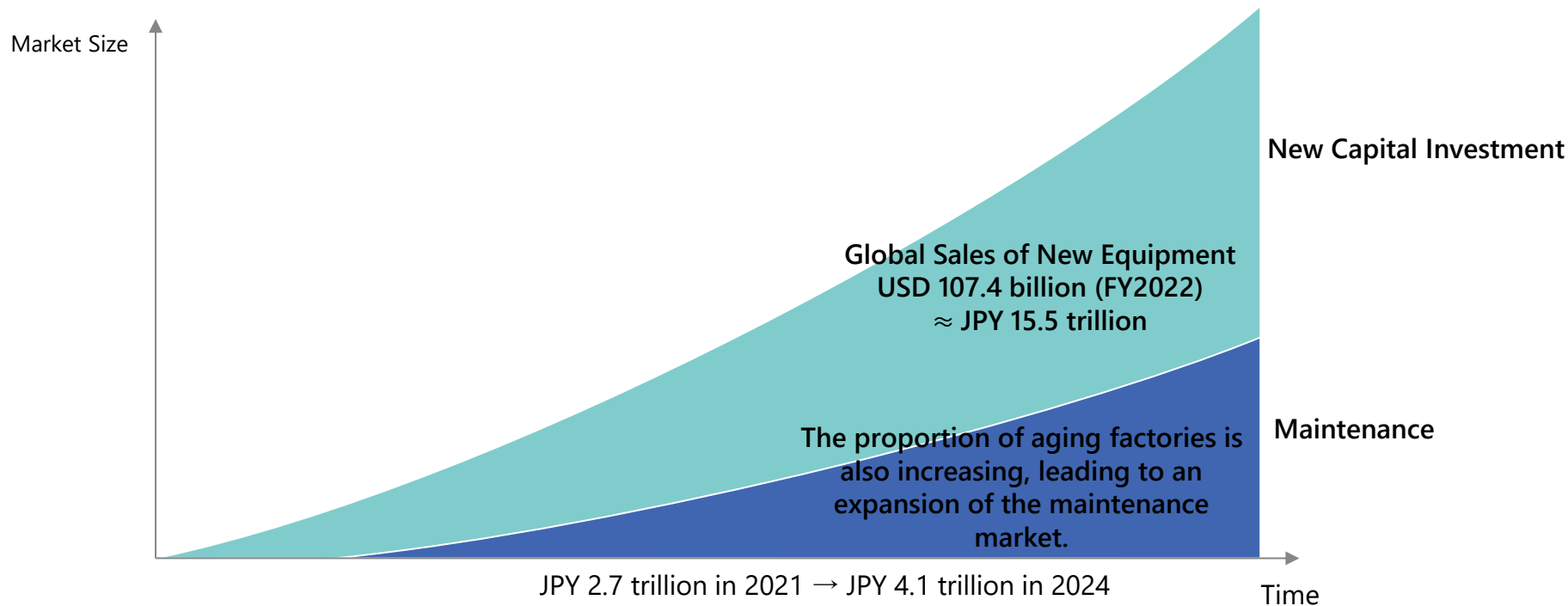


Business Background – Expansion of the Maintenance Market (Parts Procurement, Repairs, and Other Services)

As the number of both new and used semiconductor manufacturing equipment increases, demand for maintenance services to keep the equipment operational is also growing.

- Due to the structural economic fluctuation cycle known as the "Silicon Cycle" in the semiconductor industry, capital investment tends to be uneven. However, the cumulative number of fabs worldwide continues to increase, leading to the expansion of the aftermarket. As the semiconductor market grows, sourcing spare parts is becoming increasingly difficult.

New Equipment and Maintenance



Both the cross-border e-commerce platform consolidating parts information and engineering expertise are essential to society, and our company's strength lies in fulfilling both.

(Source) Market size of maintenance (after-sales service) referenced from SEMI-NET, Semiconductor Manufacturing Equipment & Post-Sales Market Yearbook.

Current Status of Domestic Semiconductor Fabs — Comparison of New and Old

The majority of domestic semiconductor fabs were built over 20 years ago and have wafer sizes of 200mm or less.

Western Japan

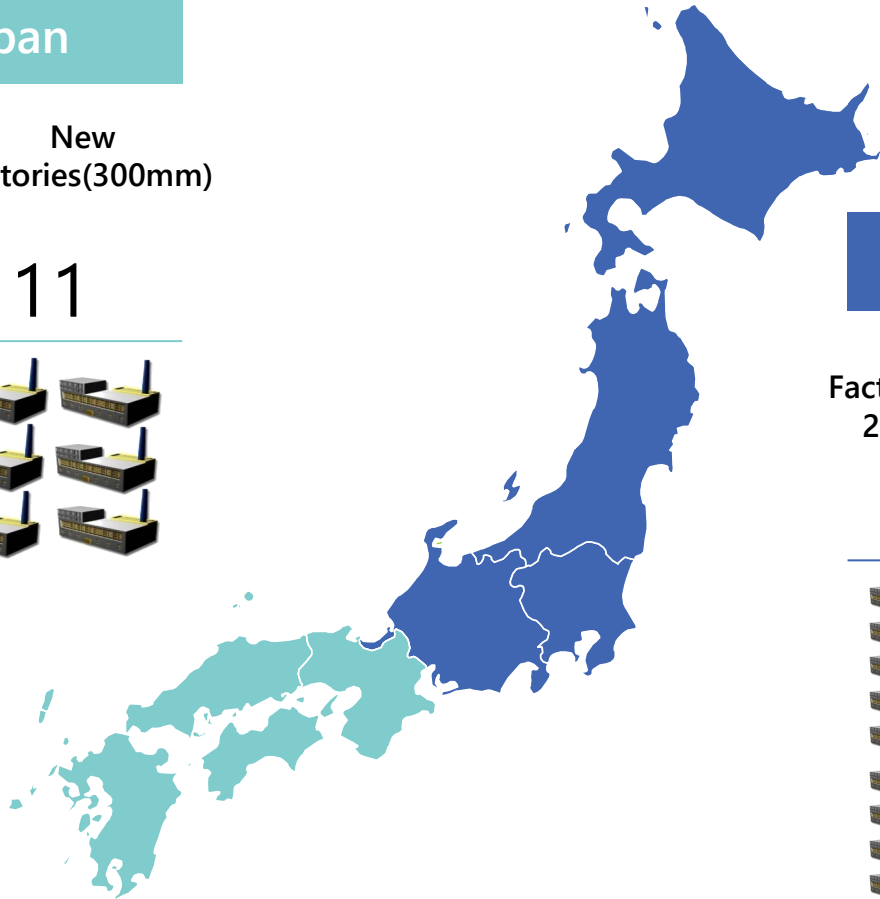
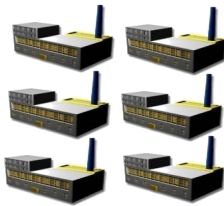
Aging
Factories(Wafer size
200mm or less)

24



New
Factories(300mm)

11

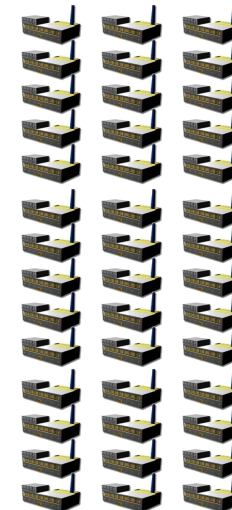


Source: Created based on the Semiconductor Fab Handbook 2025. Data aggregated by front-end device manufacturer site.

Eastern Japan

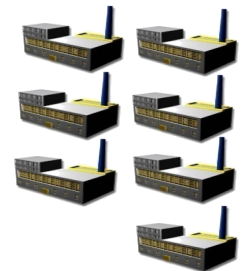
Aging
Factories(Wafer size
200mm or less)

39



New
Factories(300mm)

12



About 200mm / 300mm Wafer Size Factories

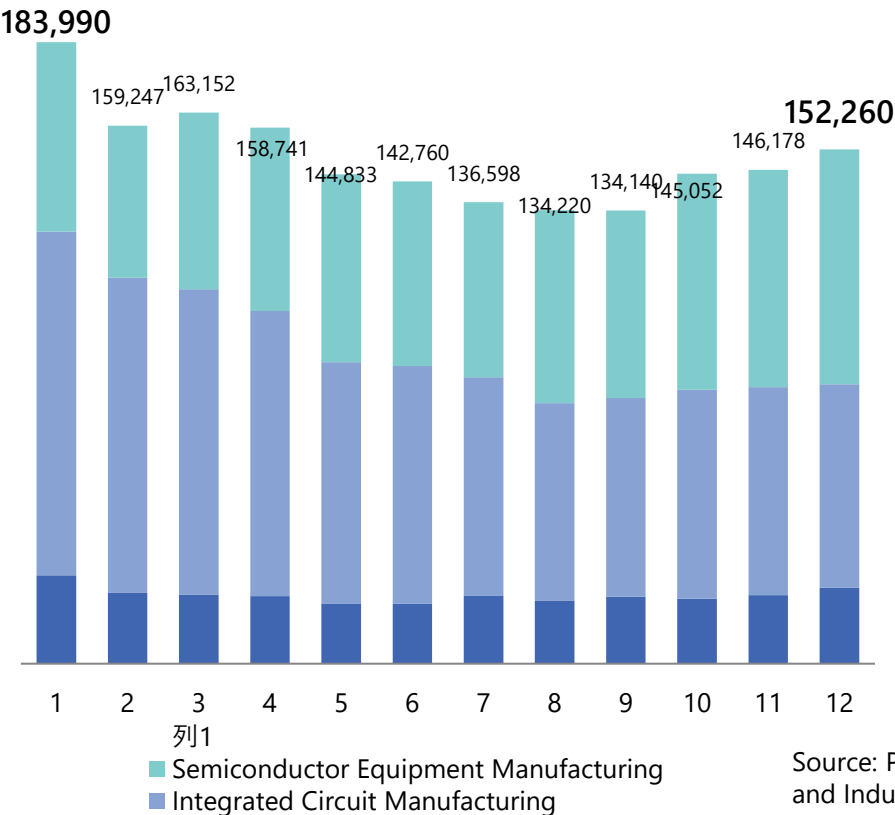
The term "millimeter" refers to the diameter size of the wafer, which is the material used to manufacture semiconductor chips. The 200mm wafer has been a widely used standard size in the past, but currently, the larger 300mm wafer, which allows for higher production efficiency, has become the mainstream. Factories using 200mm wafers often employ older technologies and are sometimes referred to as legacy fabs.

Current Status of Domestic Semiconductor Fabs — Labor Shortage in the Semiconductor Industry

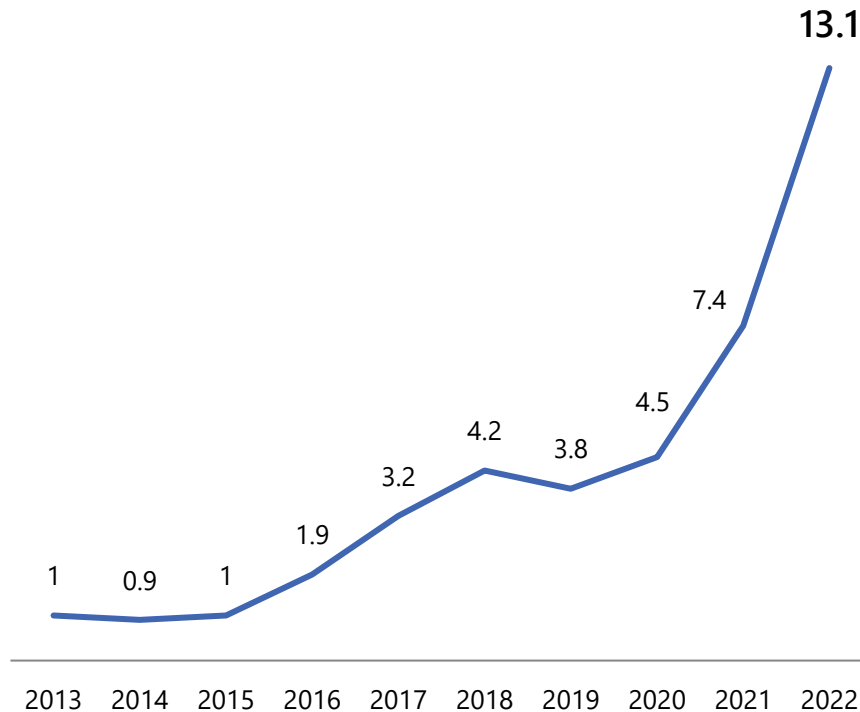
The semiconductor industry is facing a severe labor shortage.

- According to the Industrial Statistics Survey (Ministry of Economy, Trade and Industry), the number of semiconductor workers decreased from approximately 180,000 in 2008 to about 150,000 in 2019.
- Meanwhile, demand for semiconductor talent has rapidly increased, accelerating to 13.1 times the level of 2013 by 2022.
- Domestic investments are accelerating, including TSMC (Kumamoto), Rapidus (Hokkaido), and Micron (Hiroshima).

Number of Semiconductor Personnel in Japan



Job-to-Aplicant Ratio for Semiconductor-Related Engineers



Source: Prepared by our company based on the Ministry of Economy, Trade and Industry's "Economic Census for Business Activity and Industrial Statistics Survey_2-01_Industry Subclassification_Annual 2005-2020"

02 Overview of Our Business

AGENDA

- 01 Company Overview
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- 04 Competitive Landscape
- 05 Growth Strategy

Competitive Advantage

Deeply entrenched in the semiconductor industry, which has high entry barriers, through total solutions and a strong customer base.

**Establishing a unique positioning difficult for competitors to imitate,
building a strong and loyal customer base.**

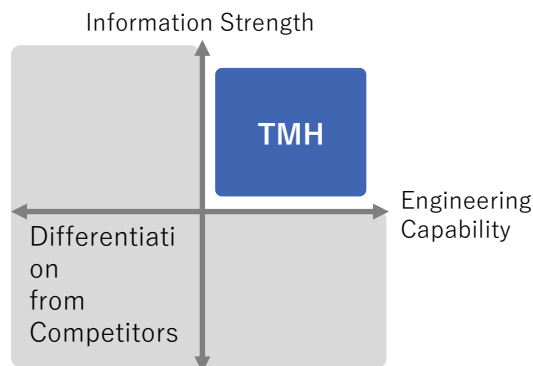
Technical knowledge accumulation

**Know-how and problem-solving capability
accumulated through direct
transactions with customers**



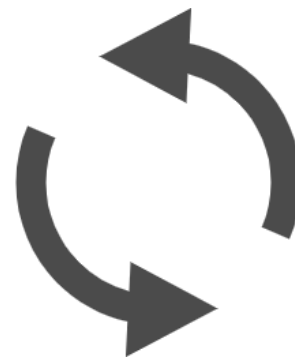
Market positioning

**Creating a market as a niche
top player in a blue ocean**



Strong continuity

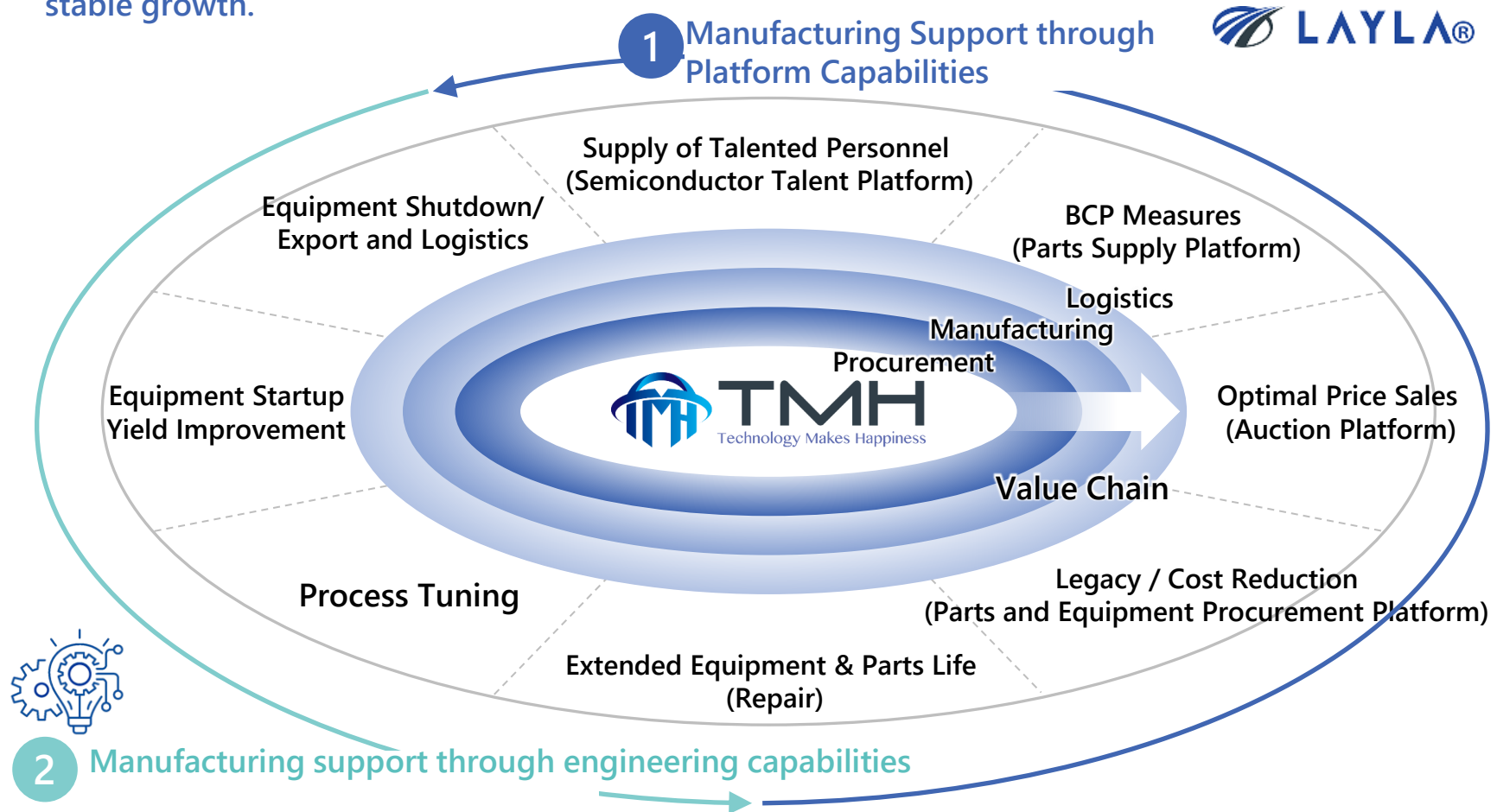
**The trust built through
problem-solving leads to
additional and ongoing
transactions.**



Accumulation of Technical and Knowledge Expertise

By addressing the diverse challenges faced by semiconductor fabs, we have become an indispensable partner for our customers.

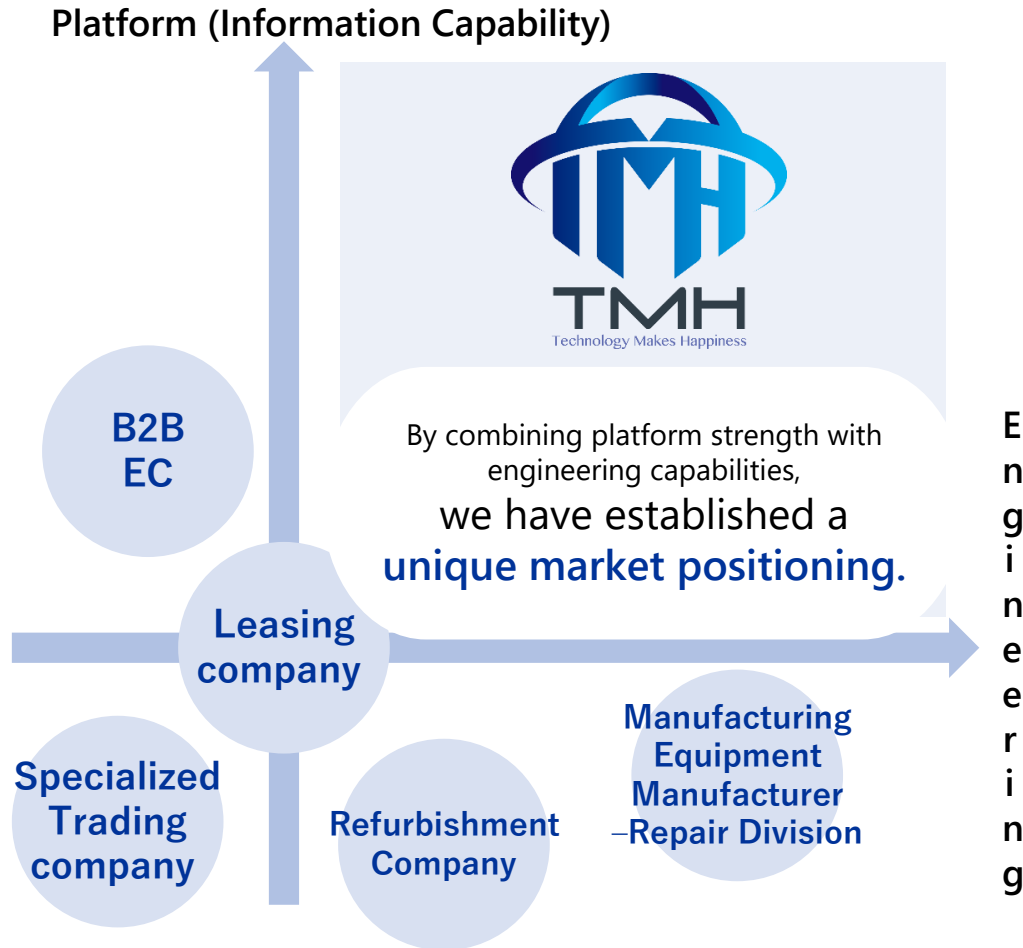
- By engaging with a wide range of projects through solving challenges faced by semiconductor fabs, we continuously enhance our know-how and problem-solving capabilities.
- As an information-centric company involved in semiconductor manufacturing, we are on a path of stable growth.



Positioning Map

Establishing a unique positioning and creating a market as a niche top player.

Positioning of Competitors and Our Company



Barriers to Entry

01 | vs Leasing Company, Trading Company

- Information strength leveraging digital services based on the platform.
- Providing advanced support such as semiconductor manufacturing equipment startup and process tuning.

02 | vs Semiconductor Equipment Manufacturers

- Equipment manufacturers provide strong support mainly to advanced fabs, but our company supports a wide range of semiconductor fabs, including legacy fabs.
- While equipment manufacturers handle only their own products, we deal with products from all semiconductor equipment manufacturers, offering a broad lineup of services.

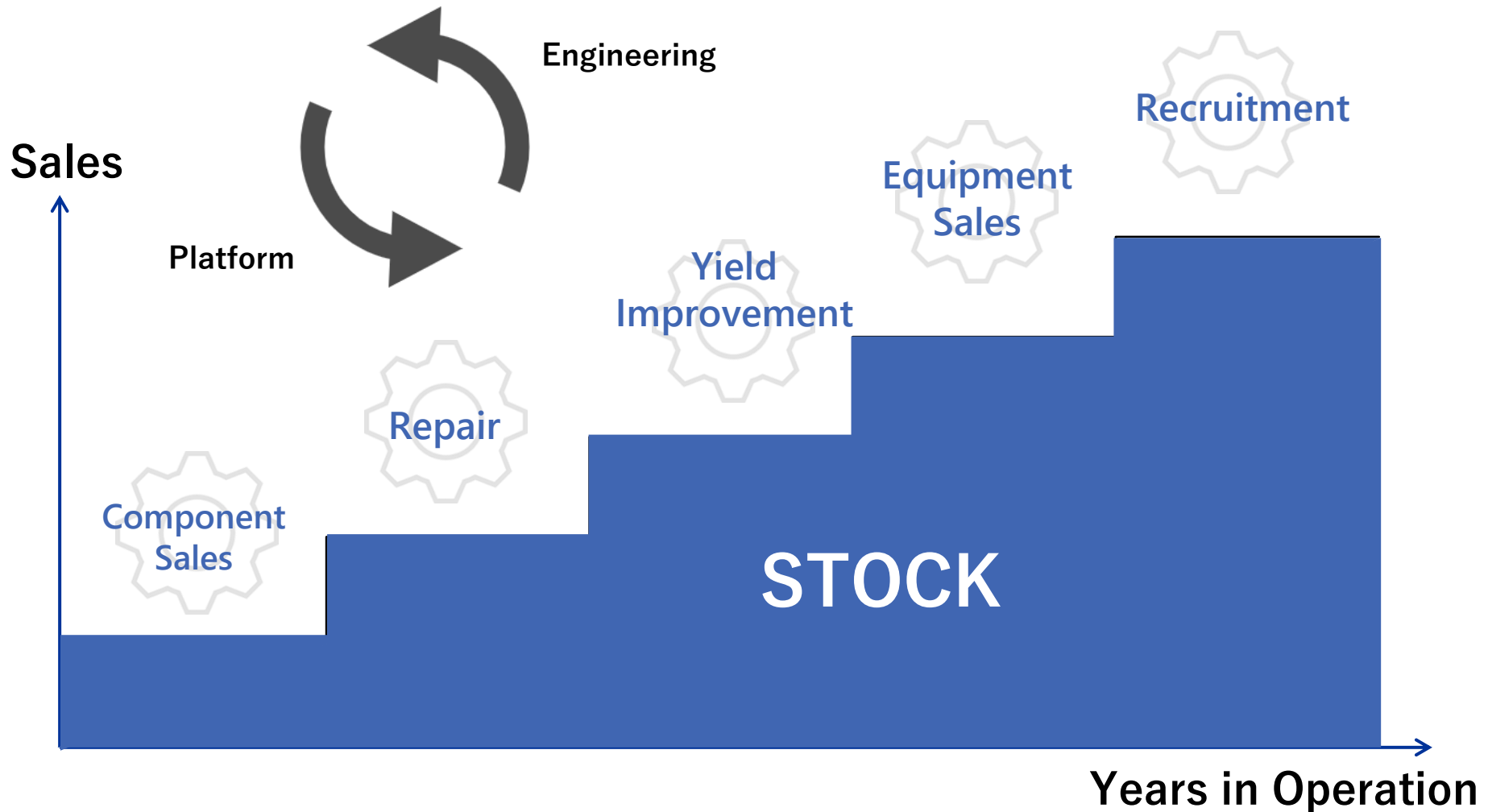
03 | vs New Entrants

- The semiconductor manufacturing field requires specialized technical expertise, and since we already have an established customer base nationwide in Japan with a significant market share, we are able to maintain high barriers to entry.

High Continuity

The trust cultivated through ongoing transactions leads to continued business and diversification opportunities.

- Through solving challenges faced by semiconductor fabs, we build strong trust relationships with customers. This leads to expanded transactions with existing clients and high-margin after-sales services, fostering long-term business partnerships.



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Growth Strategy Image

In the medium to long term, we aim to expand our business by establishing new bases, expanding our platform, and pursuing overseas expansion.

Overseas Expansion: Years 2025–2030

Starting in 2025, we will accelerate our overseas expansion, beginning with entry into India and Taiwan, aiming to establish a global market position.

Domestic Expansion: 2025–2027

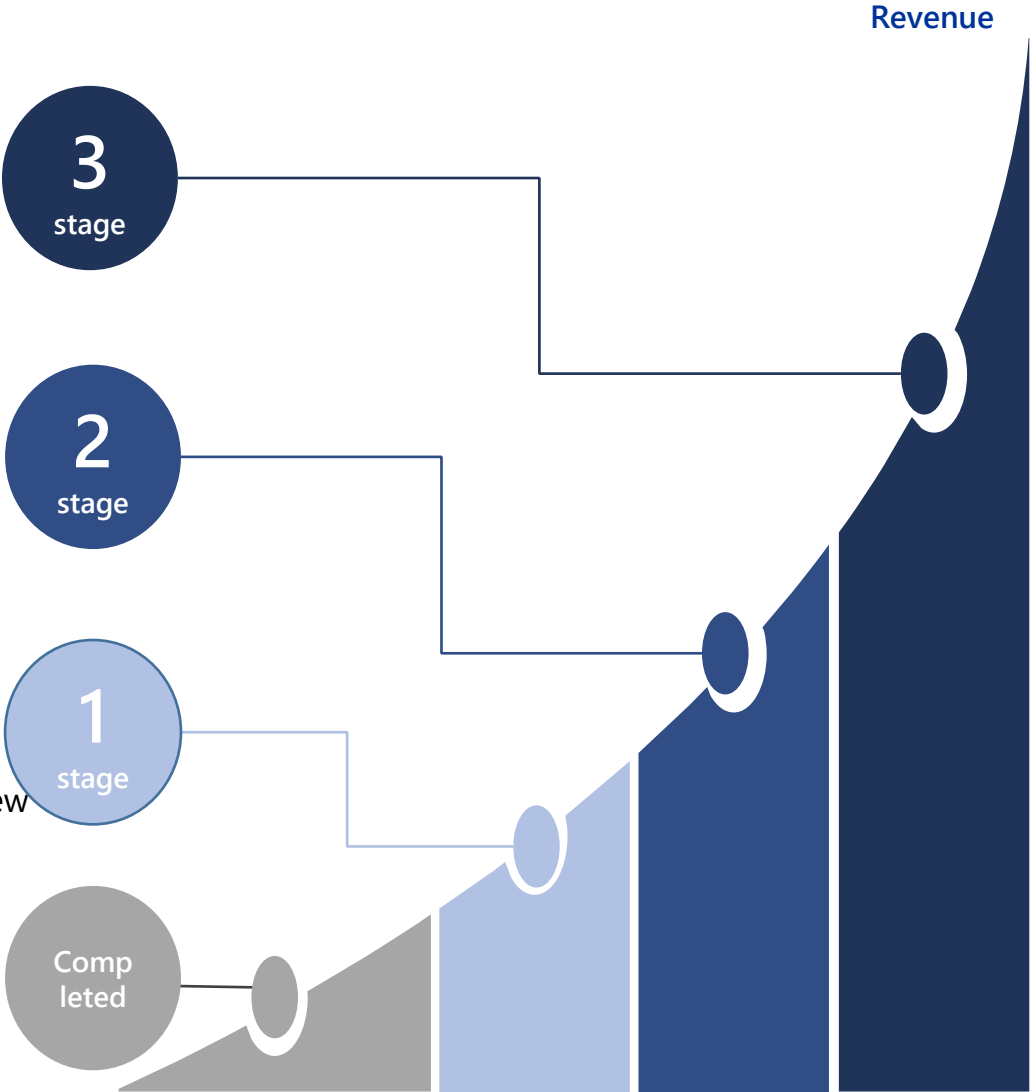
Establish bases aligned with the operational schedules of key customers’ factories. Expect revenue growth through acquisition of new customers.

Human Resources Platform Business: Fiscal Year Ending November 2025

Launched a specialized talent platform business focused on the semiconductor industry. Uncover new needs through this new business initiative.

Achieved

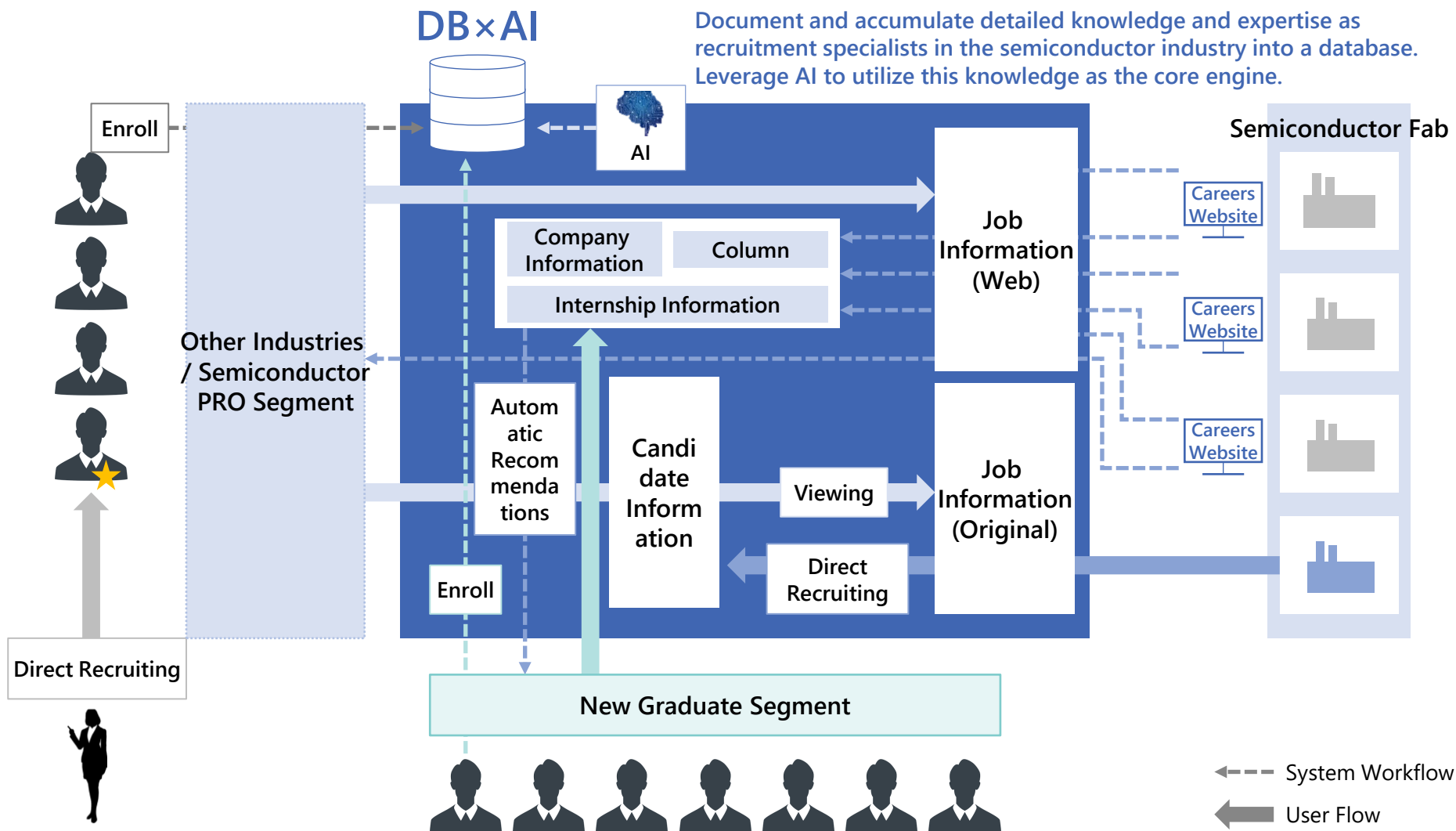
- Opened Kyushu (Kumamoto) branch in January 2024
- Released LAYLA-Auction in July 2023



Promotion of the Talent Platform Business — Short- to Mid-Term Plan for the Semiconductor Talent Platform “LAYLA-HR”

Advancing the development of a platform to address the semiconductor industry’s talent shortage challenges.

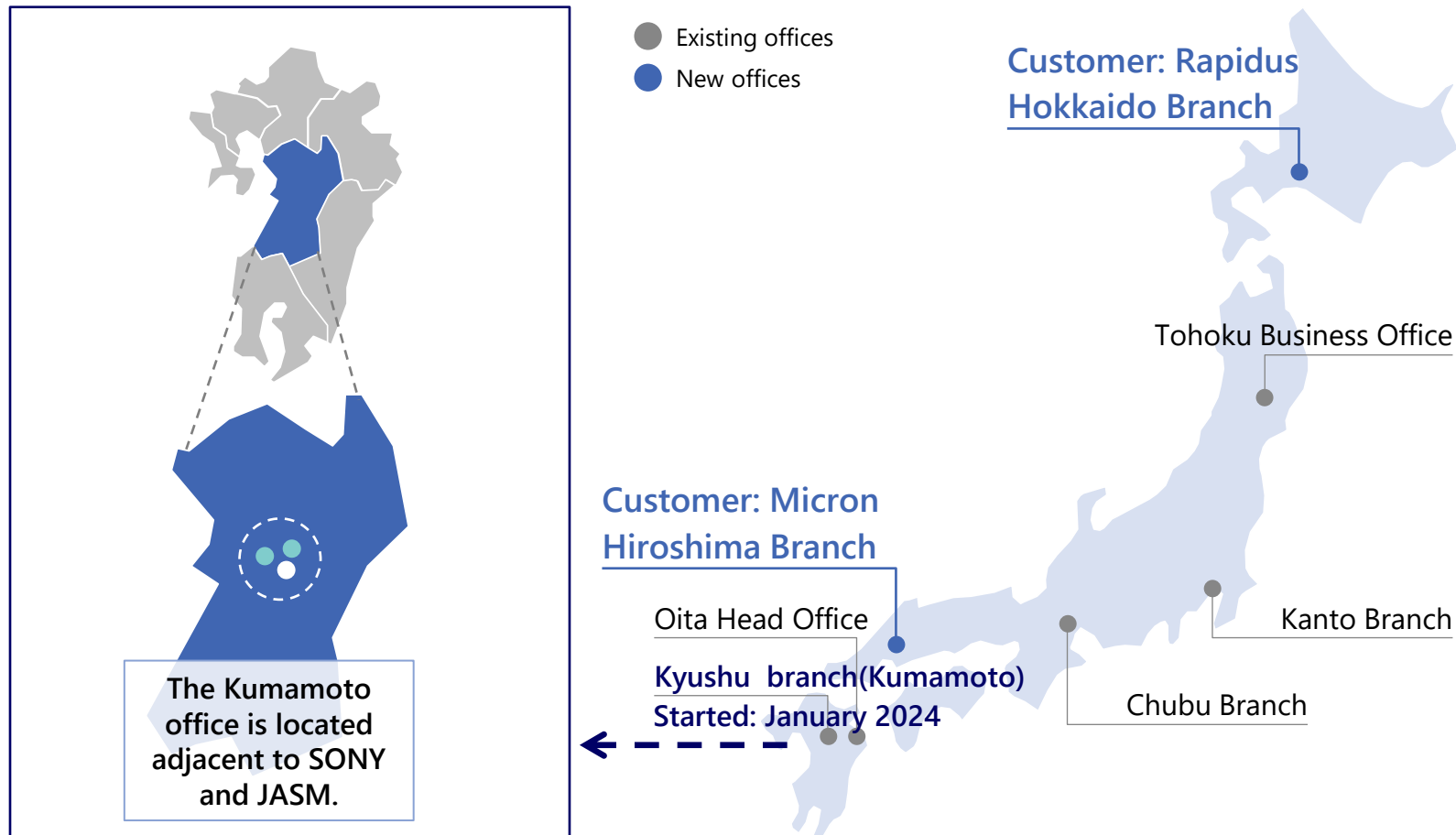
Semiconductor-Focused Talent Platform Concept (LAYLA-HR)



Expansion of Existing Business — Potential for Further Domestic Site Growth

New semiconductor factory constructions are accelerating in regions such as Hiroshima and Hokkaido.

Amid large-scale investments within Japan, our company aims to expand the market by establishing sales offices in areas adjacent to key customers!



Expansion of Sales Channels — Medium- to Long-Term Plan: Progress in Overseas Expansion

We position overseas expansion—centered on Korea and India—as a key growth driver to reinforce our business pillars.

Korea set as first overseas subsidiary base

Using the establishment of a participation framework for tenders run by a leading Korean memory maker with global share as a springboard, we expanded our global procurement network for semiconductor manufacturing equipment.



Pyeongtaek, the site of our subsidiary, is a semiconductor hub with a high concentration of plants, including factories operated by a leading Korean memory maker.

Potential

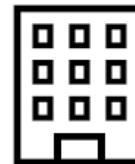
Backed by proactive government support and private investment, Korea's semiconductor market is poised for strong growth. R&D in AI chips and next-generation memory is progressing, bolstering Korea's global competitiveness.

Strategy

On July 15, 2025, we established a subsidiary in Pyeongtaek, Korea. Looking ahead to further expansion of equipment procurement in Korea and global sales, we aim to strengthen engineering-driven equipment sales and scale the cross-border e-commerce platform "LAYLA."

India Market Positioned as a Key Strategic Sales Area

In collaboration with our operations in Japan, we provide end-to-end support—from e-commerce-based parts sales and repair services to cultivating new customers for equipment sales.



Potential

India is actively promoting investment in semiconductor manufacturing plants as a national policy. A semiconductor fab is also planned to be built jointly by the Tata Group and Taiwan's Powerchip Semiconductor Manufacturing Corporation (PSMC), leading to strong demand for legacy equipment and maintenance services.

Strategy

In 2024, the company began developing its customer base in India, starting with participation in Semicon India to target market expansion. In the medium to long term, India is being considered as one of the overseas sales bases.

Mid-term Margin Target:

The company seeks to enhance profitability by expanding its business scale through new ventures and broader sales channels.

Scenario for Achieving the Margin Target in Three Years (by 2027)

- While expanding market share in equipment sales, the company aims to enhance added value through after-sales services, leading to improved profit margins.
- Significant margin improvement is expected through the expansion of parts sales and repair services, including in-house production.
- The human resource placement business maintains a high gross margin, which is expected to increase further through the development of a matching platform.



Gross Profit Margin Target 25%

Initiatives to Increase Profit Margins

- Further large-scale orders based on past achievements.
- Profitability improvement through business growth in parts sales and repair services, as well as personnel placement services, utilizing platforms.

Operating Profit Margin Target 15%

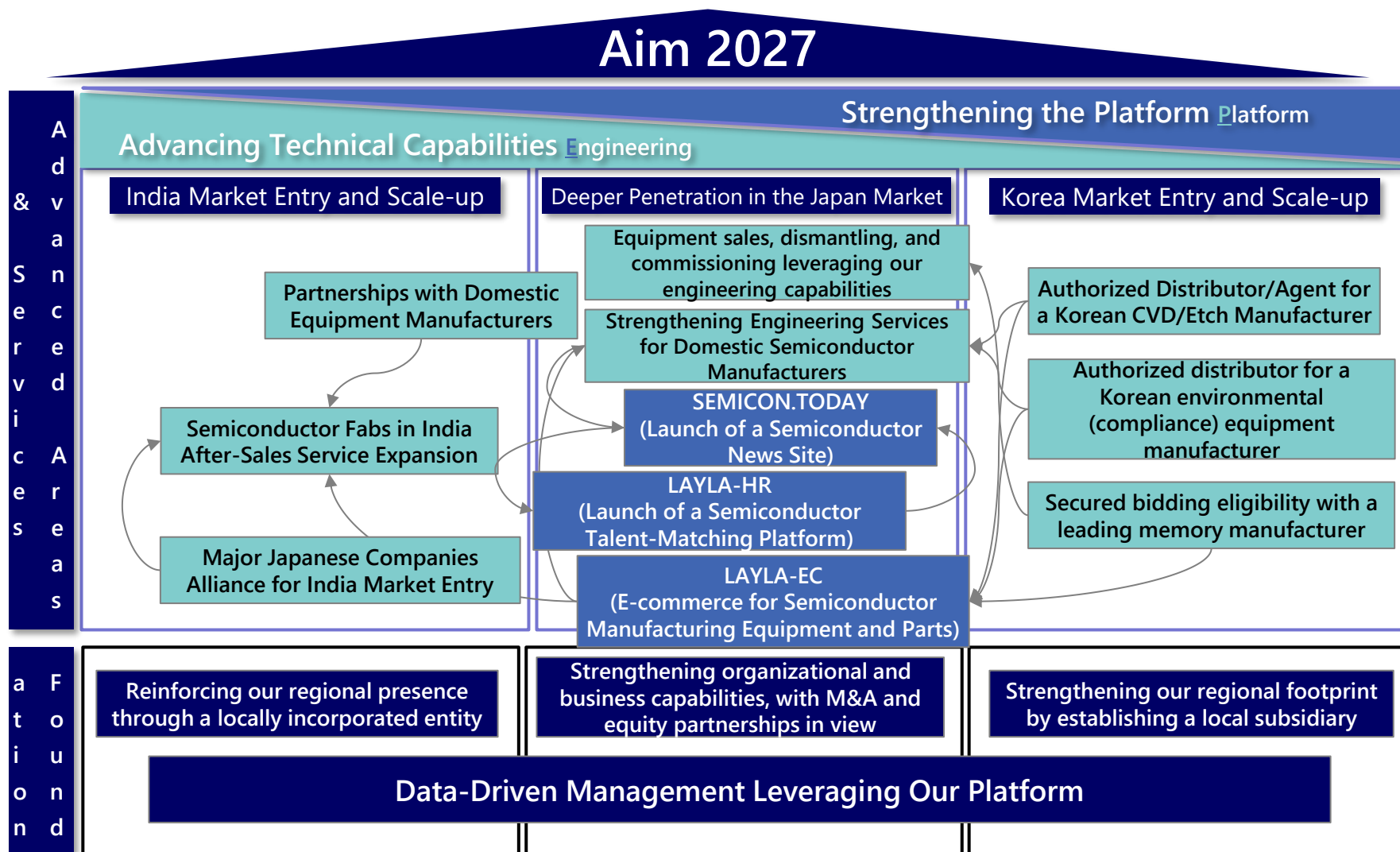
Initiatives to Increase Profit Margins

- Reduction in SG&A expense ratio as sales increase
- The company plans to expand its presence near large-scale factories and implement solution-driven sales approaches to realize a highly profitable business, while focusing on efficiency to achieve cost reductions during the growth period.

Path to Our Medium-Term Margin Target

We will broaden our markets and service offerings to upgrade the value proposition of maintenance, sustain topline growth, and target a 15% operating margin.

Sustained Revenue Growth; **25% Gross Margin**; **15% Operating Margin**



APPENDIX

Assumptions for Earnings Forecast

(Unit: Million yen)

Sales	8,366 ~ 7,871	
-Equipment Sales	6,823 ~ 6,328	<ul style="list-style-type: none"> The upper limit for equipment sales services is based on the order backlog to create the sales forecast for FY2025. The lower limit is estimated assuming that projects scheduled for the final month of the fiscal year are postponed to the following year.
-Parts Sales & Repair Services	1,535	<ul style="list-style-type: none"> The projections for parts sales and repair services are based on prior year performance and the advancement of sales activities. Sales are expected to grow in line with increased operational activity at semiconductor manufacturing plants.
Cost of Sales		<ul style="list-style-type: none"> Cost of sales is influenced by the profit margin on equipment sales, and the cost ratio fluctuates in accordance with the sales volume of parts sales and repair services.
Selling, General and Administrative Expenses (SG&A)		<ul style="list-style-type: none"> Costs are projected based on prior year performance, taking into account increases in staffing and planned expansions.
Non-operating Income and Expenses		<ul style="list-style-type: none"> From FY2024 onward, major projects like equipment sales services are primarily transacted in Japanese yen to significantly reduce foreign exchange risk. While parts sales and repair services include foreign currency transactions, the close timing between revenue recognition and receipt of payment, as well as between purchase recognition and payment, leads us to consider the FX impact negligible.

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